

SBS 1.1-COMPLIANT GAS GAUGE ENABLED WITH IMPEDANCE TRACK™ TECHNOLOGY FOR USE WITH THE bq29312A

FEATURES

- Patented Impedance Track™ Technology Accurately Measures Available Charge in Li-Ion and Li-Polymer Batteries
- Better than 1% Error Over Lifetime of the Battery
- Instant Accuracy – No Learning Cycle Required
- Supports the Smart Battery Specification SBS V1.1
- Works With the TI bq29312A Analog Front-End (AFE) Protection IC to Provide Complete Pack Electronics Solution
- Full Array of Programmable Voltage, Current, and Temperature Protection Features
- Integrated Time Base Removes Need for External Crystal with Optional Crystal Input
- Electronics for 7.2-V, 10.8-V or 14.4-V Battery Packs With Few External Components
- Based on a Powerful Low-Power RISC CPU Core With High-Performance Peripherals
- Integrated Field Programmable FLASH Memory Eliminates the Need for External Configuration Memory
- Measures Charge Flow Using a High-Resolution, 16-Bit Integrating Delta-Sigma Converter
 - Better Than 0.65 nVh of Resolution
 - Self-Calibrating
 - Offset Error Less Than 1 μ V
- Uses 16-Bit Delta-Sigma Converter for Accurate Voltage and Temperature Measurements
- Extensive Data Reporting Options For Improved System Interaction
- Optional Pulse Charging Feature for Improved Charge Times
- Drives 3-, 4- or 5-Segment LED Display for Remaining Capacity Indication
- Supports SHA-1 Authentication

- Lifetime Data Logging
- 38-Pin TSSOP (DBT)

APPLICATIONS

- Notebook PCs
- Medical and Test Equipment
- Portable Instrumentation

DESCRIPTION

The bq20z80 SBS-compliant gas gauge IC, incorporating patented Impedance Track™ technology, is designed for battery-pack or in-system installation. The bq20z80 measures and maintains an accurate record of available charge in Li-ion or Li-polymer batteries using its integrated high-performance analog peripherals. The bq20z80 monitors capacity change, battery impedance, open-circuit voltage, and other critical parameters of the battery pack, and reports the information to the system host controller over a serial-communication bus. It is designed to work with the bq29312A analog front-end (AFE) protection IC to maximize functionality and safety, and minimize component count and cost in smart battery circuits.

The Impedance Track technology continuously analyzes the battery impedance, resulting in superior gas-gauging accuracy. This enables remaining capacity to be calculated with discharge rate, temperature, and cell aging all accounted for during each stage of every cycle.

AVAILABLE OPTIONS

| T _A | PACKAGE | |
|----------------|--------------------------------|----------------------------------|
| | 38-PIN TSSOP (DBT) Tube | 38-PIN TSSOP (DBT) Tape and Reel |
| –40°C to 85°C | bq20z80DBT-V102 ⁽¹⁾ | bq20z80DBTR-V102 ⁽²⁾ |

- (1) A single tube quantity is 50 units.
 (2) A single reel quantity is 2000 units



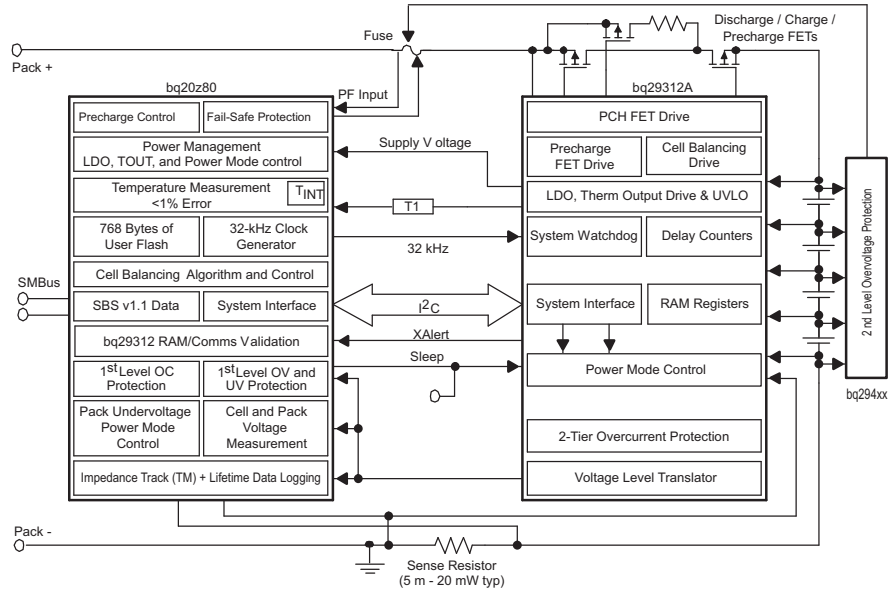
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Impedance Track is a trademark of Texas Instruments.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

SYSTEM DIAGRAM



TSSOP (DBT) (TOP VIEW)

| | | | |
|-------|----|----|-------------|
| VIN | 1 | 38 | VSSD |
| TS1 | 2 | 37 | NC |
| TS2 | 3 | 36 | NC |
| PU | 4 | 35 | CLKOUT |
| PRES | 5 | 34 | XCK1 / VSSA |
| SCLK | 6 | 33 | XCK2 / ROSC |
| SAFE | 7 | 32 | FILT |
| VDDD | 8 | 31 | VDDA |
| RBI | 9 | 30 | VSSA |
| SDATA | 10 | 29 | VSSA |
| VSSD | 11 | 28 | SR1 |
| SAFE | 12 | 27 | SR2 |
| NC | 13 | 26 | MRST |
| NC | 14 | 25 | XALERT |
| SMBC | 15 | 24 | LED1 |
| SMBD | 16 | 23 | LED2 |
| DISP | 17 | 22 | LED3 |
| PFIN | 18 | 21 | LED4 |
| VSSD | 19 | 20 | LED5 |

NC - No internal connection

TERMINAL FUNCTIONS

| TERMINAL | | I/O ⁽¹⁾ | DESCRIPTION |
|------------|--------------------------|--------------------|--|
| NO. | NAME | | |
| 1 | VIN | I | Voltage measurement input from the AFE |
| 2 | TS1 | I | 1 st Thermistor voltage input connection to monitor temperature |
| 3 | TS2 | I | 2 nd Thermistor voltage input connection to monitor temperature |
| 4 | PU | O | Output to pull up the $\overline{\text{PRES}}$ pin for system detection |
| 5 | $\overline{\text{PRES}}$ | I | Active low input to sense system insertion and typically requires additional ESD protection |
| 6 | SCLK | I/OD | Communication clock to the AFE |
| 7 | SAFE | O | Active high output to enforce additional level of safety protection; e.g., fuse blow. (Inverse of pin 12) |
| 8 | VDDD | P | Positive supply for digital circuitry and I/O pins |
| 9 | RBI | P | Backup power to the bq20z80 data registers during periods of low operating voltage. RBI accepts a storage capacitor or a battery input. |
| 10 | SDATA | I/O | Data transfer to and from the AFE |
| 12 | $\overline{\text{SAFE}}$ | O | Active low output to enforce additional level of safety protection; e.g., fuse blow. (Inverse of pin 7) |
| 13 | NC | – | Not used— leave floating |
| 14 | NC | – | Not used— leave floating |
| 15 | SMBC | I/OD | SMBus clock open-drain bidirectional pin used to clock the data transfer to and from the bq20z80 |
| 16 | SMBD | I/OD | SMBus data open-drain bidirectional pin used to transfer address and data to and from the bq20z80 |
| 17 | $\overline{\text{DISP}}$ | I | Display control for the LEDs. This pin is typically connected to bq29312A REG via a 100-k Ω resistor and a push-button switch to VSSD. |
| 18 | $\overline{\text{PFIN}}$ | I | Active low input to detect secondary protector output status and allows the bq20z80 to report the status of the 2 nd level protection output |
| 20 | LED5 | O | LED5 display segment that drives an external LED depending on the firmware configuration |
| 21 | LED4 | O | LED4 display segment that drives an external LED depending on the firmware configuration |
| 22 | LED3 | O | LED3 display segment that drives an external LED depending on the firmware configuration |
| 23 | LED2 | O | LED2 display segment that drives an external LED depending on the firmware configuration |
| 24 | LED1 | O | LED1 display segment that drives an external LED depending on the firmware configuration |
| 25 | XALERT | I | Input from bq29312A XALERT output. |
| 26 | MRST | I | Master reset input that forces the device into reset when held high |
| 27 | SR2 | IA | Connections for a small-value sense resistor to monitor the battery charge- and discharge-current flow |
| 28 | SR1 | IA | Connections for a small-value sense resistor to monitor the battery charge- and discharge-current flow |
| 31 | VDDA | P | Positive supply for analog circuitry |
| 32 | FILT | IA | Analog input connected to the external PLL filter components which are a 150-pF capacitor to V_{SSA} , in parallel with a 61.9-k Ω resistor and a 2200-pF capacitor in series. Place these components as close as possible to the bq20z80 to ensure optimal performance. |
| 33 | XCK2/ROSC | O | 32.768-kHz crystal oscillator output pin or connected to a 100k, 50ppm or better resistor if the internal oscillator is used |
| 34 | XCK1/VSSA | I | 32.768-kHz crystal oscillator input pin or connected to VSSA if the internal oscillator is used |
| 35 | CLKOUT | O | 32.768-kHz output for the bq29312. This pin should be directly connected to the AFE. |
| 36, 37 | NC | - | Not used— leave floating |
| 11, 19, 38 | VSSD | P | Negative supply for digital circuitry |
| 29, 30 | VSSA | P | Negative supply for analog circuitry. |

(1) I = Input, IA = Analog input, I/O = Input/output, I/OD = Input/Open-drain output, O = Output, OA = Analog output, P = Power

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | RANGE |
|---|---------------------------------------|-----------------------------|
| V_{DDA} and V_{DDD} relative to V_{SS} ⁽²⁾ | Supply voltage range | -0.3 V to 4.1 V |
| $V_{(IOD)}$ relative to V_{SS} ⁽²⁾ | Open-drain I/O pins | -0.3 V to 6 V |
| V_I relative to V_{SS} ⁽²⁾ | Input voltage range to all other pins | -0.3 V to $V_{DDA} + 0.3$ V |
| T_A | Operating free-air temperature range | -40°C to 85°C |
| T_{stg} | Storage temperature range | -65°C to 150°C |

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) V_{SS} refers to the common node of $V_{(SSA)}$ and $V_{(SSD)}$.

ELECTRICAL CHARACTERISTICS

$V_{DD} = 3$ V to 3.6 V, $T_A = -40$ °C to 85°C (unless otherwise noted)

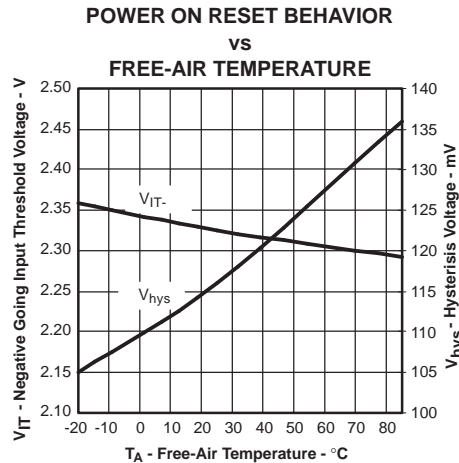
| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------|--|----------------------|-----------------|--------------------|---------------------|------|
| V_{DD} | Supply voltage | VDDA and VDDD | 3 | 3.3 | 3.6 | V |
| I_{DD} | Operating mode current | No flash programming | | 350 ⁽¹⁾ | | μA |
| | | bq20z80 + bq29312A | | 375 | | |
| $I_{(SLP)}$ | Low-power storage mode current | Sleep mode | | 8 ⁽¹⁾ | | μA |
| | | bq20z80 + bq29312A | | 28 | | |
| $I_{(SLP)}$ | Shutdown Current | Shutdown Mode | | 0.1 ⁽¹⁾ | | μA |
| | | bq20z80 + bq29312A | | 0.1 | | |
| V_{OL} | Output voltage low SMBC, SMBD, SDATA, SCLK, \overline{SAFE} , SAFE, PU | $I_{OL} = 0.5$ mA | | | 0.4 | V |
| | LED1 – LED5 | $I_{OL} = 10$ mA | | | 0.4 | V |
| V_{OH} | Output high voltage, SMBC, SMBD, SDATA, SCLK, \overline{SAFE} , SAFE, PU | $I_{OH} = -1$ mA | $V_{DD} - 0.5$ | | | V |
| V_{IL} | Input voltage low SMBC, SMBD, SDATA, SCLK, XALERT, PRES, PFIN | | -0.3 | | 0.8 | V |
| | DISP | | -0.3 | | 0.8 | V |
| V_{IH} | Input voltage high SMBC, SMBD, SDATA, SCLK, XALERT, PRES, PFIN | | 2 | | 6 | V |
| | DISP | | 2 | | $V_{DD} + 0.3$ | V |
| C_{IN} | Input capacitance | | | 5 | | pF |
| $V_{(AI1)}$ | Input voltage range VIN, TS1, TS2 | | $V_{SS} - 0.3$ | | $0.8 \times V_{DD}$ | V |
| $V_{(AI2)}$ | Input voltage range SR1, SR2 | | $V_{SS} - 0.25$ | | 0.25 | |
| $Z_{(AI1)}$ | Input impedance SR1, SR2 | 0 V–1 V | 2.5 | | | MΩ |
| $Z_{(AI2)}$ | Input impedance VIN, TS1, TS2 | 0 V–1 V | 8 | | | MΩ |

(1) This value does not include the bq29312A

POWER-ON RESET

$V_{DD} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|-----------------|-----|-----|-----|------|
| V_{IT-} Negative-going voltage input | | 2.1 | 2.3 | 2.5 | V |
| V_{HYS} Power-on reset hysteresis | | 50 | 150 | 200 | mV |



INTEGRATING ADC (Coulomb Counter) CHARACTERISTICS

$V_{DD} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|------------------------------------|-------|--------|--------|---------------|
| $V_{(SR)}$ Input voltage range, $V_{(SR2)}$ and $V_{(SR1)}$ | $V_{(SR)} = V_{(SR2)} - V_{(SR1)}$ | -0.25 | | 0.25 | V |
| $V_{(SROS)}$ Input offset | | | 1 | | μV |
| INL Integral nonlinearity error | | | 0.004% | 0.019% | |

PLL SWITCHING CHARACTERISTICS

$V_{DD} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|----------------------|-----|-----|-----|------|
| $t_{(SP)}$ Start-up time ⁽¹⁾ | 0.5% frequency error | | 2 | 5 | ms |

(1) The frequency error is measured from the trimmed frequency of the internal system clock which is 128 oscillator frequency, nominally 4.194 MHz.

OSCILLATOR

$V_{DD} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|--------|-------|-------|---------------|
| $f_{(exo)}$ Frequency error from 32.768 kHz | ROSC = 100 k Ω | -2% | 0.25% | 2% | |
| | ROSC = 100 k Ω , $V_{DD} = 3.3\text{ V}$ | -1% | 0.25% | 1% | |
| | XCK1 = 12-pF XTAL | -0.25% | | 0.25% | |
| $f_{(sxo)}$ Start-up time ⁽¹⁾ | ROSC = 100 k Ω | | | 250 | μs |
| | XCK1 = 12-pF XTAL | | | 200 | ms |

(1) The start-up time is defined as the time it takes for the oscillator output frequency to be within 1% of the specified frequency.

DATA FLASH MEMORY CHARACTERISTICS
 $V_{DD} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|--------------------------------|--------------------|--------|-----|-----|--------|
| t_{DR} | Data retention | See ⁽¹⁾ | 10 | | | Years |
| | Flash programming write-cycles | See ⁽¹⁾ | 20,000 | | | Cycles |
| $t_{(WORDPROG)}$ | Word programming time | See ⁽¹⁾ | | | 2 | ms |
| $I_{(DDPROG)}$ | Flash-write supply current | See ⁽¹⁾ | | 8 | 15 | mA |

(1) Assured by design. Not production tested

REGISTER BACKUP
 $V_{DD} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------|---|--|-----|-----|-----|------|
| $I_{(RBI)}$ | RBI data-retention input current | $V_{(RBI)} > 3\text{ V}$, $V_{DD} < V_{IT}$ | | 10 | 100 | nA |
| $V_{(RBI)}$ | RBI data-retention voltage ⁽¹⁾ | | 1.3 | | | V |

(1) Specified by design. Not production tested.

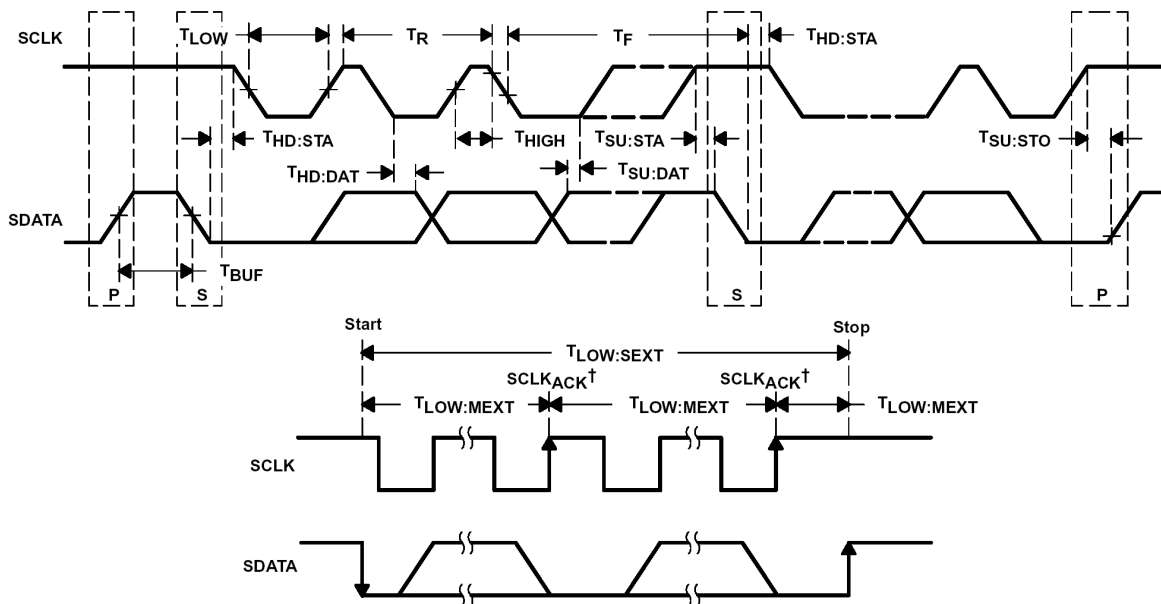
SMBus TIMING SPECIFICATIONS

$V_{DD} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------|---|--|-----|------|------|---------------|
| f_{SMB} | SMBus operating frequency | Slave mode, SMBC 50% duty cycle | 10 | | 100 | kHz |
| f_{MAS} | SMBus master clock frequency | Master mode, no clock low slave extend | | 51.2 | | |
| t_{BUF} | Bus free time between start and stop | | 4.7 | | | μs |
| $t_{HD:STA}$ | Hold time after (repeated) start | | 4 | | | |
| $t_{SU:STA}$ | Repeated start setup time | | 4.7 | | | |
| $t_{SU:STO}$ | Stop setup time | | 4 | | | |
| $t_{HD:DAT}$ | Data hold time | Receive mode | 0 | | | |
| | | Transmit mode | 300 | | | |
| $t_{SU:DAT}$ | Data setup time | | 250 | | | |
| $t_{TIMEOUT}$ | Error signal/detect | See (1) | 25 | | 35 | ms |
| t_{LOW} | Clock low period | | 4.7 | | | μs |
| t_{HIGH} | Clock high period | See (2) | 4 | | 50 | |
| $t_{LOW:SEXT}$ | Cumulative clock low slave extend time | See (3) | | | 25 | ms |
| $t_{LOW:MEXT}$ | Cumulative clock low master extend time | See (4) | | | 10 | |
| t_F | Clock/data fall time | $(V_{ILMAX} - 0.15\text{ V})$ to $(V_{IHMIN} + 0.15\text{ V})$ | | | 300 | ns |
| t_R | Clock/data rise time | 0.9 VDD to $(V_{ILMAX} - 0.15\text{ V})$ | | | 1000 | |

- (1) The bq20z80 times out when any clock low exceeds $t_{TIMEOUT}$.
- (2) $t_{HIGH:MAX}$ is minimum bus idle time. SMBC = 1 for $t > 50\ \mu\text{s}$ causes reset of any transaction involving the bq20z80 that is in progress.
- (3) $t_{LOW:SEXT}$ is the cumulative time a slave device is allowed to extend the clock cycles in one message from initial start to the stop.
- (4) $t_{LOW:MEXT}$ is the cumulative time a master device is allowed to extend the clock cycles in one message from initial start to the stop.

SMBus TIMING DIAGRAM



* SCLKACK is the acknowledge-related clock pulse generated by the master.

FEATURE SET

NOTE:

The bq20z80-V102 is designed to work with the bq29312A AFE. The bq20z80 features are only available with the bq29312A.

Primary (1st Level) Safety Features

The bq20z80 supports a wide range of battery and system protection features that can easily be configured. The primary safety features includes:

- Battery cell over/under voltage protection
- Battery pack over/under voltage protection
- 2 independent charge overcurrent protection
- 3 independent discharge overcurrent protection
- Short circuit protection
- Over temperature protection
- Host watchdog

Secondary (2nd Level) Safety Features

The secondary safety features of the bq20z80 can be used to indicate more serious faults via the SAFE (pin 7) and $\overline{\text{SAFE}}$ (pin 12) pins. These pins can be used to blow a in-line fuse to permanently disable the battery pack from charging or discharging. The secondary safety features includes:

- Safety over voltage
- Battery cell imbalance
- 2nd level protection IC input
- Safety over current
- Safety over temperature
- Open thermistor
- Charge FET and 0 Volt Charge FET fault
- Discharge FET fault
- Fuse blow failure detection
- AFE communication error
- Internal flash data error

Charge Control Features

The bq20z80 charge control features includes:

- Report the appropriate charging current needed for constant current charging and the appropriate charging voltage needed for constant voltage charging to a smart charger using SMBus broadcasts.
- Determines the chemical state of charge of each battery cell using Impedance Track™ and can reduce the charge difference of the battery cells in fully charged state of the battery pack gradually using cell balancing algorithm during charging. This prevents fully charged cells from overcharging causing excessive degradation and also increases the usable pack energy by preventing to early charge termination
- supports pre-charging/zero-volt charging
- support fast charging
- supports pulse charging
- detects charge termination
- report charging faults and also indicate charge status via charge and discharge alarms.

FEATURE SET (continued)

Gas Gauging

The bq20z80 uses the Impedance Track™ Technology to measure and calculate the available charge in battery cells. The achievable accuracy is better than the coulomb counting method over the lifetime of the battery and there is no full charge discharge learning cycle required.

See *Theory and Implementation of Impedance Track Battery Fuel-Gauging Algorithm* application note (SLUA364) for further details.

LED Display

The bq20z80 can drive 3-, 4-, or 5- segment LED display for remaining capacity indication.

LifeTime Data Logging Features

The bq20z80 offers a lifetime data logging array, where all important measurements are stored for warranty and analysis purposes. The data monitored includes:

- Lifetime maximum temperature
- Lifetime minimum temperature
- Lifetime maximum battery cell voltage
- Lifetime minimum battery cell voltage
- Lifetime maximum battery pack voltage
- Lifetime minimum battery pack voltage
- Lifetime maximum charge current
- Lifetime maximum discharge current
- Lifetime maximum charge power
- Lifetime maximum discharge power
- Lifetime maximum average discharge current
- Lifetime maximum average discharge power
- Lifetime average temperature

Authentication

The bq20z80 supports authentication by the host using SHA-1.

Power Modes

The bq20z80 supports 3 different power modes to reduce power consumption:

- In Normal Mode, the bq20z80 performs measurements, calculations, protection decisions, data update in 1 second intervals. Between these intervals, the bq20z80 is in a reduced power stage.
- In Sleep Mode, the bq20z80 performs measurements, calculations, protection decisions, data update in adjustable time intervals. Between these intervals, the bq20z80 is in a reduced power stage.
- In Shutdown Mode the bq20z80 is completely disabled.

CONFIGURATION

Oscillator Function

The oscillator of the bq20z80 can be set up for internal or external operation. On power up, the bq20z80 automatically attempts to start the internal oscillator. If a 100-k Ω resistor is not connected to ROSC (pin 33), then it attempts to start the oscillator using an external 32.768-kHz crystal.

NOTE:

Install either the 100-k Ω ROSC resistor *or* the 12-pF, 32.768-kHz crystal. Do not install both.

FEATURE SET (continued)

The performance of the internal oscillator depends on the tolerance of the 100-k Ω resistor between RSOC (pin 33) and VSSA (pin 34). Choose a resistor with a tolerance of $\pm 0.1\%$, and 50-ppm or better temperature drift. Place this resistor as close as possible to the bq20z80. If a 12-pF crystal is used, place it as close as possible to the XCK1 (pin 34) and XCK2 (pin 33) pins. If not properly implemented, the PCB layout in this area can degrade oscillator performance.

System Present Operation

The bq20z80 pulls the PU pin high periodically (1 s). Connect this pin to the $\overline{\text{PRES}}$ pin of the bq20z80 via a resistor of approximately 5 k Ω . The bq20z80 measures the $\overline{\text{PRES}}$ input during the PU-active period to determine its state. If $\overline{\text{PRES}}$ input is pulled to ground by external system, the bq20z80 detects this as system present.

BATTERY PARAMETER MEASUREMENTS

The bq20z80 uses an integrating delta-sigma analog-to-digital converter (ADC) for current measurement, and a second delta-sigma ADC for individual cell and battery voltage, and temperature measurement.

Charge and Discharge Counting

The integrating delta-sigma ADC measures the charge/discharge flow of the battery by measuring the voltage drop across a small-value sense resistor between the SR1 and SR2 pins. The integrating ADC measures bipolar signals from -0.25 V to 0.25 V. The bq20z80 detects charge activity when $V_{\text{SR}} = V_{(\text{SR1})} - V_{(\text{SR2})}$ is positive and discharge activity when $V_{\text{SR}} = V_{(\text{SR1})} - V_{(\text{SR2})}$ is negative. The bq20z80 continuously integrates the signal over time, using an internal counter. The fundamental rate of the counter is 0.65 nVh.

Voltage

The bq20z80 updates the individual series cell voltages through the bq29312A at one second intervals. The bq20z80 configures the bq29312A to connect the selected cell, cell offset, or bq29312A VREF to the CELL pin of the bq29312A, which is required to be connected to VIN of the bq20z80. The internal ADC of the bq20z80 measures the voltage, scales and calibrates it appropriately. This data is also used to calculate the impedance of the cell for the Impedance Track™ gas-gauging.

Current

The bq20z80 uses the SR1 and SR2 inputs to measure and calculate the battery charge and discharge current using a 5 m Ω to 20 m Ω typ. sense resistor.

Auto Calibration

The bq20z80 provides an auto-calibration feature to cancel the voltage offset error across SR1 and SR2 for maximum charge measurement accuracy. The bq20z80 performs auto-calibration when the SMBus lines stay low continuously for a minimum of 5 s.

Temperature

The bq20z80 TS1 and TS2 inputs, in conjunction with two identical NTC thermistors (default are Semitec 103AT), measure the battery environmental temperature. The bq20z80 can also be configured to use its internal temperature sensor.

COMMUNICATIONS

The bq20z80 uses SMBus v1.1 with Master Mode and package error checking (PEC) options per the SBS specification.

SMBus On and Off State

The bq20z80 detects an SMBus off state when SMBC and SMBD are logic-low greater than an adjustable period of time. Clearing this state requires either SMBC or SMBD to transition high. Within 1 ms, the communication bus is available.

FEATURE SET (continued)
SBS and Dataflash Values
Table 1. SBS COMMANDS

| SBS Cmd | Mode | Name | Format | Size in Bytes | Min Value | Max Value | Default Value | Unit |
|---------|------|------------------------|--------------|---------------|-----------|-----------|-------------------|--------------|
| 0x00 | R/W | ManufacturerAccess | hex | 2 | 0x0000 | 0xffff | — | |
| 0x01 | R/W | RemainingCapacityAlarm | unsigned int | 2 | 0 | 65535 | — | mAh or 10mWh |
| 0x02 | R/W | RemainingTimeAlarm | unsigned int | 2 | 0 | 65535 | — | min |
| 0x03 | R/W | BatteryMode | hex | 2 | 0x0000 | 0xffff | — | |
| 0x04 | R/W | AtRate | signed int | 2 | -32768 | 32767 | — | mA or 10mW |
| 0x05 | R | AtRateTimeToFull | unsigned int | 2 | 0 | 65535 | — | min |
| 0x06 | R | AtRateTimeToEmpty | unsigned int | 2 | 0 | 65535 | — | min |
| 0x07 | R | AtRateOK | unsigned int | 2 | 0 | 65535 | — | |
| 0x08 | R | Temperature | unsigned int | 2 | 0 | 65535 | — | 0.1°K |
| 0x09 | R | Voltage | unsigned int | 2 | 0 | 20000 | — | mV |
| 0x0a | R | Current | signed int | 2 | -32768 | 32767 | — | mA |
| 0x0b | R | AverageCurrent | signed int | 2 | -32768 | 32767 | — | mA |
| 0x0c | R | MaxError | unsigned int | 1 | 0 | 100 | — | % |
| 0x0d | R | RelativeStateOfCharge | unsigned int | 1 | 0 | 100 | — | % |
| 0x0e | R | AbsoluteStateOfCharge | unsigned int | 1 | 0 | 100 | — | % |
| 0x0f | R | RemainingCapacity | unsigned int | 2 | 0 | 65535 | — | mAh or 10mWh |
| 0x10 | R | FullChargeCapacity | unsigned int | 2 | 0 | 65535 | — | mAh or 10mWh |
| 0x11 | R | RunTimeToEmpty | unsigned int | 2 | 0 | 65535 | — | min |
| 0x12 | R | AverageTimeToEmpty | unsigned int | 2 | 0 | 65535 | — | min |
| 0x13 | R | AverageTimeToFull | unsigned int | 2 | 0 | 65535 | — | min |
| 0x14 | R | ChargingCurrent | unsigned int | 2 | 0 | 65535 | — | mA |
| 0x15 | R | ChargingVoltage | unsigned int | 2 | 0 | 65535 | — | mV |
| 0x16 | R | BatteryStatus | unsigned int | 2 | 0x0000 | 0xffff | — | |
| 0x17 | R/W | CycleCount | unsigned int | 2 | 0 | 65535 | — | |
| 0x18 | R/W | DesignCapacity | unsigned int | 2 | 0 | 65535 | — | mAh or 10mWh |
| 0x19 | R/W | DesignVoltage | unsigned int | 2 | 7000 | 16000 | 14400 | mV |
| 0x1a | R/W | SpecificationInfo | unsigned int | 2 | 0x0000 | 0xffff | 0x0031 | |
| 0x1b | R/W | ManufactureDate | unsigned int | 2 | 0 | 65535 | 0 | |
| 0x1c | R/W | SerialNumber | hex | 2 | 0x0000 | 0xffff | 0x0001 | |
| 0x20 | R/W | ManufacturerName | String | 11+1 | — | — | Texas Instruments | ASCII |
| 0x21 | R/W | DeviceName | String | 7+1 | — | — | bq20z80 | ASCII |
| 0x22 | R/W | DeviceChemistry | String | 4+1 | — | — | LION | ASCII |
| 0x23 | R | ManufacturerData | String | 14+1 | — | — | — | ASCII |
| 0x2f | R/W | Authenticate | String | 20+1 | — | — | — | ASCII |
| 0x3c | R | CellVoltage4 | unsigned int | 2 | 0 | 65535 | | mV |
| 0x3d | R | CellVoltage3 | unsigned int | 2 | 0 | 65535 | | mV |
| 0x3e | R | CellVoltage2 | unsigned int | 2 | 0 | 65535 | | mV |
| 0x3f | R | CellVoltage1 | unsigned int | 2 | 0 | 65535 | | mV |

Table 2. EXTENDED SBS COMMANDS

| SBS Cmd | Mode | Name | Format | Size in Bytes | Min Value | Max Value | Default Value | Unit |
|---------|------|--------------------|--------------|---------------|------------|------------|---------------|-------|
| 0x45 | R | AFEData | String | 11+1 | — | — | — | ASCII |
| 0x46 | R/W | FETControl | hex | 1 | 0x00 | 0xff | — | |
| 0x4f | R | StateOfHealth | unsigned int | 1 | 0 | 100 | — | % |
| 0x50 | R | SafetyAlert | hex | 2 | 0x0000 | 0xffff | — | |
| 0x51 | R | SafetyStatus | hex | 2 | 0x0000 | 0xffff | — | |
| 0x52 | R | PFAlert | hex | 2 | 0x0000 | 0xffff | — | |
| 0x53 | R | PFStatus | hex | 2 | 0x0000 | 0xffff | — | |
| 0x54 | R | OperationStatus | hex | 2 | 0x0000 | 0xffff | — | |
| 0x55 | R | ChargingStatus | hex | 2 | 0x0000 | 0xffff | — | |
| 0x57 | R | ResetData | hex | 2 | 0x0000 | 0xffff | — | |
| 0x58 | R | WDRResetData | unsigned int | 2 | 0 | 65535 | — | |
| 0x5a | R | PackVoltage | unsigned int | 2 | 0 | 65535 | — | mV |
| 0x5d | R | AverageVoltage | unsigned int | 2 | 0 | 65535 | — | mV |
| 0x60 | R/W | UnSealKey | hex | 4 | 0x00000000 | 0xffffffff | — | |
| 0x62 | R/W | PFKey | hex | 4 | 0x00000000 | 0xffffffff | — | |
| 0x63 | R/W | AuthenKey3 | hex | 4 | 0x00000000 | 0xffffffff | — | |
| 0x64 | R/W | AuthenKey2 | hex | 4 | 0x00000000 | 0xffffffff | — | |
| 0x65 | R/W | AuthenKey1 | hex | 4 | 0x00000000 | 0xffffffff | — | |
| 0x66 | R/W | AuthenKey0 | hex | 4 | 0x00000000 | 0xffffffff | — | |
| 0x70 | R/W | ManufacturerInfo | String | 8+1 | — | — | — | |
| 0x71 | R/W | SenseResistor | unsigned int | 2 | 0 | 65535 | — | μΩ |
| 0x77 | R/W | DataflashClass | hex | 2 | 0x0000 | 0xffff | — | |
| 0x78 | R/W | DataFlashSubClass1 | hex | 32 | — | — | — | |
| 0x79 | R/W | DataFlashSubClass2 | hex | 32 | — | — | — | |
| 0x7a | R/W | DataFlashSubClass3 | hex | 32 | — | — | — | |
| 0x7b | R/W | DataFlashSubClass4 | hex | 32 | — | — | — | |
| 0x7c | R/W | DataFlashSubClass5 | hex | 32 | — | — | — | |
| 0x7d | R/W | DataFlashSubClass6 | hex | 32 | — | — | — | |
| 0x7e | R/W | DataFlashSubClass7 | hex | 32 | — | — | — | |
| 0x7f | R/W | DataFlashSubClass8 | hex | 32 | — | — | — | |

Table 3. DATAFLASH VALUES

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units |
|------------------|--------------|----------|--------|---------------|-----------|-----------|-----------|---------------|-------|
| 1st Level Safety | 0 | Voltage | 0 | COV Threshold | U2 | 3700 | 5000 | 4300 | mV |
| | | | 2 | COV Time | U1 | 0 | 60 | 2 | Sec |
| | | | 3 | COV Recovery | U2 | 0 | 4400 | 3900 | mV |
| | | | 5 | COV Delta | U1 | 0 | 200 | 20 | mV |
| | | | 6 | COV Temp. Hys | U1 | 0 | 250 | 100 | 0.1°C |
| | | | 7 | POV Threshold | U2 | 0 | 18000 | 17500 | mV |
| | | | 9 | POV Time | U1 | 0 | 60 | 2 | Sec |
| | | | 10 | POV Recovery | U2 | 0 | 17000 | 16000 | mV |
| | | | 12 | CUV Threshold | U2 | 0 | 3500 | 2200 | mV |
| | | | 14 | CUV Time | U1 | 0 | 60 | 2 | Sec |
| | | | 15 | CUV Recovery | U2 | 0 | 3600 | 3000 | mV |
| | | | 17 | PUV Threshold | U2 | 0 | 16000 | 11000 | mV |
| | | | 19 | PUV Time | U1 | 0 | 60 | 2 | Sec |
| 20 | PUV Recovery | U2 | 0 | 16000 | 12000 | mV | | | |

Table 3. DATAFLASH VALUES (continued)

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units | | | |
|------------------|-----------------------------|-------------------|------------------|------------------------|-----------|-----------|-----------------------|---------------|-------|-------|-------|-----|
| 1st Level Safety | 1 | Current | 0 | OC (1st Tier) Chg | U2 | 0 | 20000 | 6000 | mA | | | |
| | | | 2 | OC (1st Tier) Chg Time | U1 | 0 | 60 | 2 | sec | | | |
| | | | 3 | OC Chg Recovery | I2 | -1000 | 1000 | 200 | mA | | | |
| | | | 5 | OC (1st Tier) Dsg | U2 | 0 | 20000 | 6000 | mA | | | |
| | | | 7 | OC (1st Tier) Dsg Time | U1 | 0 | 60 | 2 | sec | | | |
| | | | 8 | OC Dsg Recovery | U2 | 0 | 1000 | 200 | mA | | | |
| | | | 10 | OC (2nd Tier) Chg | U2 | 0 | 20000 | 8000 | mA | | | |
| | | | 12 | OC (2nd Tier) Chg Time | U1 | 0 | 60 | 2 | Sec | | | |
| | | | 13 | OC (2nd Tier) Dsg | U2 | 0 | 22000 | 8000 | mA | | | |
| | | | 15 | OC (2nd Tier) Dsg Time | U1 | 0 | 60 | 2 | Sec | | | |
| | | | 16 | Current Recovery Time | U1 | 0 | 60 | 8 | Sec | | | |
| | | | 17 | AFE OC Dsg | H1 | 0x00 | 0x1f | 0x12 | hex | | | |
| | | | 18 | AFE OC Dsg Time | H1 | 0x00 | 0x0f | 0x0f | hex | | | |
| | | | 19 | AFE OC Dsg Recovery | U2 | 10 | 1000 | 100 | mA | | | |
| | | | 21 | AFE SC Chg Cfg | H1 | 0x00 | 0xff | 0x77 | hex | | | |
| 22 | AFE SC Dsg Cfg | H1 | 0x00 | 0xff | 0x77 | hex | | | | | | |
| 23 | AFE SC Recovery | U2 | 0 | 200 | 1 | mA | | | | | | |
| 1st Level Safety | 2 | Temperature | 0 | Over Temp Chg | U2 | 0 | 1200 | 550 | 0.1°C | | | |
| | | | 2 | OT Chg Time | U1 | 0 | 60 | 2 | Sec | | | |
| | | | 3 | OT Chg Recovery | U2 | 0 | 1200 | 500 | 0.1°C | | | |
| | | | 5 | Over Temp Dsg | U2 | 0 | 1200 | 600 | 0.1°C | | | |
| | | | 7 | OT Dsg Time | U1 | 0 | 60 | 2 | Sec | | | |
| | | | 8 | OT Dsg Recovery | U2 | 0 | 1200 | 550 | 0.1°C | | | |
| | | | 1st Level Safety | 3 | Host Comm | 0 | Host Watchdog Timeout | U1 | 0 | 255 | 0 | Sec |
| | | | 2nd Level Safety | 16 | Voltage | 0 | SOV Threshold | U2 | 0 | 20000 | 18000 | mV |
| 2 | SOV Time | U1 | | | | 0 | 30 | 0 | Sec | | | |
| 3 | Cell Imbalance Current | U1 | | | | 0 | 200 | 5 | mA | | | |
| 4 | Cell Imbalance Fail Voltage | U2 | | | | 0 | 5000 | 1000 | mV | | | |
| 6 | Cell Imbalance Time | U1 | | | | 0 | 30 | 0 | Sec | | | |
| 7 | Battery Rest Time | U2 | | | | 0 | 65535 | 1800 | Sec | | | |
| 9 | PFIN Detect Time | U1 | | | | 0 | 30 | 0 | Sec | | | |
| 2nd Level Safety | 17 | Current | 0 | SOC Chg | U2 | 0 | 30000 | 10000 | mA | | | |
| | | | 2 | SOC Chg Time | U1 | 0 | 30 | 0 | Sec | | | |
| | | | 3 | SOC Dsg | U2 | 0 | 30000 | 10000 | mA | | | |
| | | | 5 | SOC Dsg Time | U1 | 0 | 30 | 0 | Sec | | | |
| 2nd Level Safety | 18 | Temperature | 0 | SOT Chg | U2 | 0 | 1200 | 650 | 0.1°C | | | |
| | | | 2 | SOT Chg Time | U1 | 0 | 30 | 0 | Sec | | | |
| | | | 3 | SOT Dsg | U2 | 0 | 1200 | 750 | 0.1°C | | | |
| | | | 5 | SOT Dsg Time | U1 | 0 | 30 | 0 | Sec | | | |
| | | | 6 | Open Thermistor | I2 | -1000 | 1200 | -333 | 0.1°C | | | |
| | | | 8 | Open Time | I1 | 0 | 30 | 0 | Sec | | | |
| 2nd Level Safety | 19 | FET Verification | 0 | FET Fail Limit | U2 | 0 | 500 | 20 | mA | | | |
| | | | 2 | FET Fail Time | U1 | 0 | 30 | 0 | Sec | | | |
| 2nd Level Safety | 20 | AFE Verification | 0 | AFE Check Time | U1 | 0 | 255 | 0 | Sec | | | |
| | | | 1 | AFE Fail Limit | U1 | 0 | 255 | 10 | cnt | | | |
| | | | 2 | AFE Fail Recovery Time | U1 | 0 | 255 | 20 | Sec | | | |
| | | | 3 | AFE Init Retry Limit | U1 | 0 | 255 | 6 | num | | | |
| | | | 4 | AFE Init Limit | U1 | 0 | 255 | 20 | cnt | | | |
| 2nd Level Safety | 21 | Fuse Verification | 0 | Fuse Fail Limit | U2 | 0 | 20 | 2 | mA | | | |
| | | | 2 | Fuse Fail Time | U1 | 0 | 30 | 0 | Sec | | | |

Table 3. DATAFLASH VALUES (continued)

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units |
|----------------|-------------|--------------------|--------|--------------------------|-----------|-----------|-----------|---------------|---------|
| Charge Control | 32 | Charge Inhibit Cfg | 0 | Chg Inhibit Temp Low | I2 | -400 | 1200 | 0 | 0.1°C |
| | | | 2 | Chg Inhibit Temp High | I2 | -400 | 1200 | 450 | 0.1°C |
| | | | 4 | Temp Hys | I2 | 0 | 100 | 10 | 0.1°C |
| Charge Control | 33 | Pre-Charge Cfg | 0 | Pre-chg Current | U2 | 0 | 2000 | 250 | mA |
| | | | 2 | Pre-chg Temp | I2 | -400 | 1200 | 120 | 0.1°C |
| | | | 4 | Pre-chg Voltage | U2 | 0 | 20000 | 3000 | mV |
| | | | 6 | Recovery Voltage | U2 | 0 | 20000 | 3100 | mV |
| Charge Control | 34 | Fast Charge Cfg | 0 | Fast Charge Current | U2 | 0 | 10000 | 4000 | mA |
| | | | 2 | Charging Voltage | U2 | 0 | 20000 | 16800 | mV |
| | | | 4 | Over Charging Voltage | U2 | 0 | 2000 | 500 | mV |
| | | | 6 | Delta Temp | I2 | 0 | 500 | 50 | 0.1°C |
| | | | 8 | Suspend Low Temp | I2 | -400 | 1200 | -50 | 0.1°C |
| | | | 10 | Suspend High Temp | I2 | -400 | 1200 | 550 | 0.1°C |
| Charge Control | 35 | Pulse Charge Cfg | 0 | Turn ON Voltage | U2 | 0 | 5000 | 4150 | mV |
| | | | 2 | Turn OFF Voltage | U2 | 0 | 5000 | 4250 | mV |
| | | | 4 | Max ON Pulse Time | U1 | 0 | 240 | 240 | S/4 |
| | | | 5 | Min OFF Pulse Time | U1 | 0 | 240 | 0 | S/4 |
| | | | 6 | Max OFF Voltage | U2 | 0 | 5000 | 4270 | mV |
| Charge Control | 36 | Termination Cfg. | 0 | Maintenance Current | U2 | 0 | 1000 | 0 | mA |
| | | | 2 | Taper Current | U2 | 0 | 1000 | 250 | mA |
| | | | 6 | Termination Voltage | U2 | 0 | 1000 | 300 | mV |
| | | | 8 | Current Taper Window | U1 | 0 | 60 | 40 | Sec |
| | | | 9 | TCA Set % | I1 | -1 | 100 | -1 | % |
| | | | 10 | TCA Clear % | I1 | -1 | 100 | 95 | % |
| | | | 11 | FC Set % | I1 | -1 | 100 | -1 | % |
| 12 | FC Clear % | I1 | -1 | 100 | 98 | % | | | |
| Charge Control | 37 | Cell Balancing Cfg | 0 | Min Cell Deviation | U2 | 0 | 65535 | 1750 | Sec/mAH |
| Charge Control | 38 | Charging Faults | 0 | Over Charging Voltage | U2 | 0 | 3000 | 500 | mV |
| | | | 2 | Over Charging Volt Time | U1 | 0 | 60 | 2 | Sec |
| | | | 3 | Over Charging Current | U2 | 0 | 2000 | 500 | mA |
| | | | 5 | Over Charging Curr Time | U1 | 0 | 60 | 2 | Sec |
| | | | 6 | Over Charging Curr Recov | U2 | 0 | 2000 | 100 | mA |
| | | | 8 | Depleted Voltage | U2 | 0 | 16000 | 8000 | mV |
| | | | 10 | Depleted Voltage Time | U1 | 0 | 60 | 2 | Sec |
| | | | 11 | Depleted Recovery | U2 | 0 | 16000 | 8500 | mV |
| | | | 13 | Over Charge Capacity | U2 | 0 | 4000 | 300 | mAh |
| | | | 15 | Over Charge Recovery | U2 | 0 | 100 | 2 | mAh |
| | | | 17 | FC-MTO | U2 | 0 | 65535 | 10800 | Sec |
| | | | 19 | PC-MTO | U2 | 0 | 65535 | 3600 | Sec |
| | | | 21 | Charge Fault Cfg | H1 | 0x00 | 0xff | 0 | |

Table 3. DATAFLASH VALUES (continued)

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units | | | |
|-------------------|-------------------|-----------------------|-------------|---------------------------|-------------------|-----------|---------------|---------------|--------|--------|--------|--|
| SBS Configuration | 48 | Data | 0 | Rem Cap Alarm | U2 | 0 | 700 | 300 | mAh | | | |
| | | | 2 | Rem Time Alarm | U2 | 0 | 30 | 10 | Min | | | |
| | | | 4 | Init Battery Mode | H2 | 0x0000 | 0xffff | 0x0081 | hex | | | |
| | | | 6 | Design Voltage | U2 | 7000 | 18000 | 14400 | mV | | | |
| | | | 8 | Spec Info | H2 | 0x0000 | 0xffff | 0x0031 | hex | | | |
| | | | 10 | Manuf Date | U2 | 0 | 65355 | 0 | date | | | |
| | | | 12 | Ser. Num. | H2 | 0x0000 | 0xffff | 0x0001 | hex | | | |
| | | | 14 | Cycle Count | U2 | 0 | 65355 | 0 | cnt | | | |
| | | | 16 | CC Threshold | I2 | 100 | 32767 | 4400 | mAh | | | |
| | | | 18 | CC % | U1 | 0 | 100 | 90 | % | | | |
| | | | 19 | CF MaxError Limit | U1 | 0 | 100 | 100 | % | | | |
| | | | 20 | Design Capacity | U2 | 0 | 65355 | 4400 | mAh | | | |
| | | | 22 | Design Energy | U2 | 0 | 65355 | 6336 | 10mWh | | | |
| | | | 24 | Manuf Name | S12 | - | - | Texas Inst. | | | | |
| | | | 36 | Device Name | S8 | - | - | bq20z80 | | | | |
| 44 | Device Chemistry | S5 | - | - | LION | | | | | | | |
| SBS Configuration | 49 | Configuration | 0 | TDA Set % | I1 | -1 | 100 | 6 | % | | | |
| | | | 1 | TDA Clear % | I1 | -1 | 100 | 8 | % | | | |
| | | | 2 | FD Set % | I1 | -1 | 100 | 2 | % | | | |
| | | | 3 | FD Clear % | I1 | -1 | 100 | 5 | % | | | |
| | | | 4 | TDA Set Volt Threshold | U2 | 0 | 16800 | 5000 | mV | | | |
| | | | 6 | TDA Set Volt Time | U1 | 0 | 60 | 5 | Sec | | | |
| | | | 7 | TDA Clear Volt | U2 | 0 | 16800 | 5500 | mV | | | |
| | | | 9 | FD Set Volt Threshold | U2 | 0 | 16800 | 5000 | mV | | | |
| | | | 11 | FD Volt Time | U1 | 0 | 60 | 5 | Sec | | | |
| | | | 12 | FD Clear Volt | U2 | 0 | 16800 | 5500 | mV | | | |
| | | | System Data | 56 | Manufacturer Data | 0 | Pack Lot Code | H2 | 0x0000 | 0xffff | 0x0000 | |
| | | | | | | 2 | PCB Lot Code | H2 | 0x0000 | 0xffff | 0x0000 | |
| 4 | Firmware Version | H2 | | | | 0x0000 | 0xffff | 0x0000 | | | | |
| 6 | Hardware Revision | H2 | | | | 0x0000 | 0xffff | 0x0000 | | | | |
| 8 | Cell Revision | H2 | | | | 0x0000 | 0xffff | 0x0000 | | | | |
| System Data | 58 | Manufacturer Info | 0 | Manuf. Info | S9 | - | - | 12345678 | | | | |
| System Data | 59 | LifeTime Data | 0 | Lifetime Max Temp | I2 | 0 | 1400 | 300 | 0.1°C | | | |
| | | | 2 | Lifetime Min Temp | I2 | -600 | 1400 | 200 | 0.1°C | | | |
| | | | 4 | Lifetime Max Cell Voltage | U2 | 0 | 65535 | 3500 | mV | | | |
| | | | 6 | Lifetime Min Cell Voltage | U2 | 0 | 65535 | 3200 | mV | | | |
| | | | 8 | Lifetime Max Pack Voltage | U2 | 0 | 65535 | 14000 | mV | | | |
| | | | 10 | Lifetime Min Pack Voltage | U2 | 0 | 65535 | 12800 | mV | | | |
| | | | 12 | Lifetime Max Chg Current | I2 | -32768 | 32767 | 1500 | mA | | | |
| | | | 14 | Lifetime Max Dsg Current | I2 | -32768 | 32767 | -3000 | mA | | | |
| | | | 16 | Lifetime Max Chg Power | I2 | -32768 | 32767 | 1500 | 10mW | | | |
| | | | 18 | Lifetime Max Dsg Power | I2 | -32768 | 32767 | -1500 | 10mW | | | |
| | | | 22 | Life Max AvgDsg Cur | I2 | -32768 | 32767 | -1000 | mA | | | |
| | | | 26 | Life Max AvgDsg Pow | I2 | -32768 | 32767 | -1500 | 10mW | | | |
| | | | 28 | Lifetime Avg Temp | I2 | 0 | 1400 | 250 | 0.1°C | | | |
| System Data | 60 | LifeTime Temp Samples | 0 | LT Temp Samples | U4 | 0 | 140000000 | 0 | num | | | |

Table 3. DATAFLASH VALUES (continued)

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units |
|---------------|--------------------|--------------------|--------|-------------------------|-----------|-----------|-----------|---------------|-------|
| Configuration | 64 | Registers | 0 | Operation Cfg A | H2 | 0x0000 | 0xffff | 0x0F29 | |
| | | | 2 | Operation Cfg B | H2 | 0x0000 | 0xffff | 0x6440 | |
| | | | 4 | Permanent Fail Cfg | H2 | 0x0000 | 0xffff | 0x0000 | |
| | | | 6 | Non-Removable Cfg | H2 | 0x0000 | 0xffff | 0x0000 | hex |
| LED Support | 67 | LED Cfg | 0 | LED Flash Rate | U2 | 0 | 65535 | 512 | 500µs |
| | | | 2 | LED Blink Rate | U2 | 0 | 65535 | 1024 | 500µs |
| | | | 4 | LED Delay | U2 | 1 | 65535 | 100 | 500µs |
| | | | 6 | LED Hold Time | U1 | 0 | 255 | 4 | s |
| | | | 7 | CHG Flash Alarm | I1 | -1 | 101 | 10 | % |
| | | | 8 | CHG Thresh 1 | I1 | -1 | 101 | 0 | % |
| | | | 9 | CHG Thresh 2 | I1 | -1 | 101 | 20 | % |
| | | | 10 | CHG Thresh 3 | I1 | -1 | 101 | 40 | % |
| | | | 11 | CHG Thresh 4 | I1 | -1 | 101 | 60 | % |
| | | | 12 | CHG Thresh 5 | I1 | -1 | 101 | 80 | % |
| | | | 13 | DSG Flash Alarm | I1 | -1 | 101 | 10 | % |
| | | | 14 | DSG Thresh 1 | I1 | -1 | 101 | 0 | % |
| | | | 15 | DSG Thresh 2 | I1 | -1 | 101 | 20 | % |
| | | | 16 | DSG Thresh 3 | I1 | -1 | 101 | 40 | % |
| 17 | DSG Thresh 4 | I1 | -1 | 101 | 60 | % | | | |
| 18 | DSG Thresh 5 | I1 | -1 | 101 | 60 | % | | | |
| Power | 68 | Power | 0 | Flash Update OK Voltage | U2 | 6000 | 20000 | 7500 | mV |
| | | | 2 | Shutdown Voltage | U2 | 5000 | 20000 | 7000 | mV |
| | | | 4 | Shutdown Time | U1 | 0 | 60 | 10 | Sec |
| | | | 5 | Charger Present | U2 | 0 | 23000 | 12000 | mV |
| | | | 7 | Sleep Current | U2 | 0 | 100 | 10 | mA |
| | | | 9 | Bus Low Time | U1 | 0 | 255 | 5 | Sec |
| | | | 10 | Cal Inhibit Temp Low | I2 | -400 | 1200 | 50 | 0.1°C |
| | | | 12 | Cal Inhibit Temp High | I2 | -400 | 1200 | 450 | 0.1°C |
| | | | 14 | Sleep Voltage Time | U1 | 0 | 100 | 5 | Sec |
| 15 | Sleep Current Time | U1 | 0 | 255 | 20 | Sec | | | |
| Gas Gauging | 80 | IT Cfg | 0 | Load Select | U1 | 0 | 255 | 3 | num |
| | | | 1 | Load Mode | U1 | 0 | 255 | 0 | num |
| | | | 45 | Term Voltage | I2 | -32768 | 32767 | 12000 | mV |
| | | | 60 | User Rate-mA | I2 | -9000 | -2000 | 0 | mA |
| | | | 62 | User Rate-mW | I2 | -14000 | -3000 | 0 | 10mW |
| | | | 64 | Reserve Cap-mAh | I2 | 0 | 9000 | 0 | mAh |
| 66 | Reserve Cap-mWh | I2 | 0 | 14000 | 0 | 10mWh | | | |
| Gas Gauging | 81 | Current Thresholds | 0 | Dsg Current Threshold | U2 | 0 | 2000 | 100 | mA |
| | | | 2 | Chg Current Threshold | U2 | 0 | 2000 | 50 | mA |
| | | | 4 | Quit Current | U2 | 0 | 1000 | 10 | mA |
| | | | 6 | Dsg Relax Time | U1 | 0 | 255 | 1 | Sec |
| | | | 7 | Chg Relax Time | U1 | 0 | 255 | 60 | Sec |

Table 3. DATAFLASH VALUES (continued)

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units |
|-------------|--------------|----------|--------|----------------|-----------|-----------|-----------|---------------|-----------|
| Gas Gauging | 82 | State | 0 | Qmax Cell 0 | U2 | 0 | 65535 | 4400 | mAh |
| | | | 2 | Qmax Cell 1 | U2 | 0 | 65535 | 4400 | mAh |
| | | | 4 | Qmax Cell 2 | U2 | 0 | 65535 | 4400 | mAh |
| | | | 6 | Qmax Cell 3 | U2 | 0 | 65535 | 4400 | mAh |
| | | | 8 | Qmax Pack | U2 | 0 | 65535 | 4400 | mAh |
| | | | 12 | Update Status | H1 | 0x00 | 0x06 | 0x00 | num |
| | | | 21 | Avg I Last Run | I2 | -32768 | 32767 | -2000 | mA |
| | | | 23 | Avg P Last Run | I2 | -32768 | 32767 | -3022 | 10mW |
| | | | 25 | Delta Voltage | I2 | -32768 | 32767 | 0 | mV |
| Ra Table | 88 | R_a0 | 0 | Cell0 R_a flag | H2 | 0x0000 | 0xffff | 0xff55 | |
| | | | 2 | Cell0 R_a 0 | I2 | -32768 | 32767 | 160 | mΩ at 0°C |
| | | | 4 | Cell0 R_a 1 | I2 | -32768 | 32767 | 166 | mΩ at 0°C |
| | | | 6 | Cell0 R_a 2 | I2 | -32768 | 32767 | 153 | mΩ at 0°C |
| | | | 8 | Cell0 R_a 3 | I2 | -32768 | 32767 | 151 | mΩ at 0°C |
| | | | 10 | Cell0 R_a 4 | I2 | -32768 | 32767 | 145 | mΩ at 0°C |
| | | | 12 | Cell0 R_a 5 | I2 | -32768 | 32767 | 152 | mΩ at 0°C |
| | | | 14 | Cell0 R_a 6 | I2 | -32768 | 32767 | 176 | mΩ at 0°C |
| | | | 16 | Cell0 R_a 7 | I2 | -32768 | 32767 | 204 | mΩ at 0°C |
| | | | 18 | Cell0 R_a 8 | I2 | -32768 | 32767 | 222 | mΩ at 0°C |
| | | | 20 | Cell0 R_a 9 | I2 | -32768 | 32767 | 254 | mΩ at 0°C |
| | | | 22 | Cell0 R_a 10 | I2 | -32768 | 32767 | 315 | mΩ at 0°C |
| | | | 24 | Cell0 R_a 11 | I2 | -32768 | 32767 | 437 | mΩ at 0°C |
| | | | 26 | Cell0 R_a 12 | I2 | -32768 | 32767 | 651 | mΩ at 0°C |
| | | | 28 | Cell0 R_a 13 | I2 | -32768 | 32767 | 1001 | mΩ at 0°C |
| 30 | Cell0 R_a 14 | I2 | -32768 | 32767 | 1458 | mΩ at 0°C | | | |
| Ra Table | 89 | R_a1 | 0 | Cell1 R_a flag | H2 | 0x0000 | 0xffff | 0xff55 | |
| | | | 2 | Cell1 R_a 0 | I2 | -32768 | 32767 | 160 | mΩ at 0°C |
| | | | 4 | Cell1 R_a 1 | I2 | -32768 | 32767 | 166 | mΩ at 0°C |
| | | | 6 | Cell1 R_a 2 | I2 | -32768 | 32767 | 153 | mΩ at 0°C |
| | | | 8 | Cell1 R_a 3 | I2 | -32768 | 32767 | 151 | mΩ at 0°C |
| | | | 10 | Cell1 R_a 4 | I2 | -32768 | 32767 | 145 | mΩ at 0°C |
| | | | 12 | Cell1 R_a 5 | I2 | -32768 | 32767 | 152 | mΩ at 0°C |
| | | | 14 | Cell1 R_a 6 | I2 | -32768 | 32767 | 176 | mΩ at 0°C |
| | | | 16 | Cell1 R_a 7 | I2 | -32768 | 32767 | 204 | mΩ at 0°C |
| | | | 18 | Cell1 R_a 8 | I2 | -32768 | 32767 | 222 | mΩ at 0°C |
| | | | 20 | Cell1 R_a 9 | I2 | -32768 | 32767 | 254 | mΩ at 0°C |
| | | | 22 | Cell1 R_a 10 | I2 | -32768 | 32767 | 315 | mΩ at 0°C |
| | | | 24 | Cell1 R_a 11 | I2 | -32768 | 32767 | 437 | mΩ at 0°C |
| | | | 26 | Cell1 R_a 12 | I2 | -32768 | 32767 | 651 | mΩ at 0°C |
| | | | 28 | Cell1 R_a 13 | I2 | -32768 | 32767 | 1001 | mΩ at 0°C |
| 30 | Cell1 R_a 14 | I2 | -32768 | 32767 | 1458 | mΩ at 0°C | | | |
| Ra Table | 90 | R_a2 | 0 | Cell2 R_a flag | H2 | 0x0000 | 0xffff | 0xff55 | |
| | | | 2 | Cell2 R_a 0 | I2 | -32768 | 32767 | 160 | mΩ at 0°C |
| | | | 4 | Cell2 R_a 1 | I2 | -32768 | 32767 | 166 | mΩ at 0°C |
| | | | 6 | Cell2 R_a 2 | I2 | -32768 | 32767 | 153 | mΩ at 0°C |
| | | | 8 | Cell2 R_a 3 | I2 | -32768 | 32767 | 151 | mΩ at 0°C |
| | | | 10 | Cell2 R_a 4 | I2 | -32768 | 32767 | 145 | mΩ at 0°C |
| | | | 12 | Cell2 R_a 5 | I2 | -32768 | 32767 | 152 | mΩ at 0°C |
| | | | 14 | Cell2 R_a 6 | I2 | -32768 | 32767 | 176 | mΩ at 0°C |
| | | | 16 | Cell2 R_a 7 | I2 | -32768 | 32767 | 204 | mΩ at 0°C |

Table 3. DATAFLASH VALUES (continued)

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units |
|----------|-------------|----------|--------|-----------------|-----------|-----------|-----------|---------------|-----------|
| | | | 18 | Cell2 R_a 8 | I2 | -32768 | 32767 | 222 | mΩ at 0°C |
| | | | 20 | Cell2 R_a 9 | I2 | -32768 | 32767 | 254 | mΩ at 0°C |
| | | | 22 | Cell2 R_a 10 | I2 | -32768 | 32767 | 315 | mΩ at 0°C |
| | | | 24 | Cell2 R_a 11 | I2 | -32768 | 32767 | 437 | mΩ at 0°C |
| | | | 26 | Cell2 R_a 12 | I2 | -32768 | 32767 | 651 | mΩ at 0°C |
| | | | 28 | Cell2 R_a 13 | I2 | -32768 | 32767 | 1001 | mΩ at 0°C |
| | | | 30 | Cell2 R_a 14 | I2 | -32768 | 32767 | 1458 | mΩ at 0°C |
| Ra Table | 91 | R_a3 | 0 | Cell3 R_a flag | H2 | 0x0000 | 0xffff | 0xff55 | |
| | | | 2 | Cell3 R_a 0 | I2 | -32768 | 32767 | 160 | mΩ at 0°C |
| | | | 4 | Cell3 R_a 1 | I2 | -32768 | 32767 | 166 | mΩ at 0°C |
| | | | 6 | Cell3 R_a 2 | I2 | -32768 | 32767 | 153 | mΩ at 0°C |
| | | | 8 | Cell3 R_a 3 | I2 | -32768 | 32767 | 151 | mΩ at 0°C |
| | | | 10 | Cell3 R_a 4 | I2 | -32768 | 32767 | 145 | mΩ at 0°C |
| | | | 12 | Cell3 R_a 5 | I2 | -32768 | 32767 | 152 | mΩ at 0°C |
| | | | 14 | Cell3 R_a 6 | I2 | -32768 | 32767 | 176 | mΩ at 0°C |
| | | | 16 | Cell3 R_a 7 | I2 | -32768 | 32767 | 204 | mΩ at 0°C |
| | | | 18 | Cell3 R_a 8 | I2 | -32768 | 32767 | 222 | mΩ at 0°C |
| | | | 20 | Cell3 R_a 9 | I2 | -32768 | 32767 | 254 | mΩ at 0°C |
| | | | 22 | Cell3 R_a 10 | I2 | -32768 | 32767 | 315 | mΩ at 0°C |
| | | | 24 | Cell3 R_a 11 | I2 | -32768 | 32767 | 437 | mΩ at 0°C |
| | | | 26 | Cell3 R_a 12 | I2 | -32768 | 32767 | 651 | mΩ at 0°C |
| | | | 28 | Cell3 R_a 13 | I2 | -32768 | 32767 | 1001 | mΩ at 0°C |
| | | | 30 | Cell3 R_a 14 | I2 | -32768 | 32767 | 1458 | mΩ at 0°C |
| Ra Table | 92 | R_a0x | 0 | xCell0 R_a flag | H2 | 0x0000 | 0xffff | 0xffff | |
| | | | 2 | xCell0 R_a 0 | I2 | -32768 | 32767 | 160 | mΩ at 0°C |
| | | | 4 | xCell0 R_a 1 | I2 | -32768 | 32767 | 166 | mΩ at 0°C |
| | | | 6 | xCell0 R_a 2 | I2 | -32768 | 32767 | 153 | mΩ at 0°C |
| | | | 8 | xCell0 R_a 3 | I2 | -32768 | 32767 | 151 | mΩ at 0°C |
| | | | 10 | xCell0 R_a 4 | I2 | -32768 | 32767 | 145 | mΩ at 0°C |
| | | | 12 | xCell0 R_a 5 | I2 | -32768 | 32767 | 152 | mΩ at 0°C |
| | | | 14 | xCell0 R_a 6 | I2 | -32768 | 32767 | 176 | mΩ at 0°C |
| | | | 16 | xCell0 R_a 7 | I2 | -32768 | 32767 | 204 | mΩ at 0°C |
| | | | 18 | xCell0 R_a 8 | I2 | -32768 | 32767 | 222 | mΩ at 0°C |
| | | | 20 | xCell0 R_a 9 | I2 | -32768 | 32767 | 254 | mΩ at 0°C |
| | | | 22 | xCell0 R_a 10 | I2 | -32768 | 32767 | 315 | mΩ at 0°C |
| | | | 24 | xCell0 R_a 11 | I2 | -32768 | 32767 | 437 | mΩ at 0°C |
| | | | 26 | xCell0 R_a 12 | I2 | -32768 | 32767 | 651 | mΩ at 0°C |
| | | | 28 | xCell0 R_a 13 | I2 | -32768 | 32767 | 1001 | mΩ at 0°C |
| | | | 30 | xCell0 R_a 14 | I2 | -32768 | 32767 | 1458 | mΩ at 0°C |
| Ra Table | 93 | R_a1x | 0 | xCell1 R_a flag | H2 | 0x0000 | 0xffff | 0xffff | |
| | | | 2 | xCell1 R_a 0 | I2 | -32768 | 32767 | 160 | mΩ at 0°C |
| | | | 4 | xCell1 R_a 1 | I2 | -32768 | 32767 | 166 | mΩ at 0°C |
| | | | 6 | xCell1 R_a 2 | I2 | -32768 | 32767 | 153 | mΩ at 0°C |
| | | | 8 | xCell1 R_a 3 | I2 | -32768 | 32767 | 151 | mΩ at 0°C |
| | | | 10 | xCell1 R_a 4 | I2 | -32768 | 32767 | 145 | mΩ at 0°C |
| | | | 12 | xCell1 R_a 5 | I2 | -32768 | 32767 | 152 | mΩ at 0°C |
| | | | 14 | xCell1 R_a 6 | I2 | -32768 | 32767 | 176 | mΩ at 0°C |
| | | | 16 | xCell1 R_a 7 | I2 | -32768 | 32767 | 204 | mΩ at 0°C |
| | | | 18 | xCell1 R_a 8 | I2 | -32768 | 32767 | 222 | mΩ at 0°C |
| | | | 20 | xCell1 R_a 9 | I2 | -32768 | 32767 | 254 | mΩ at 0°C |

Table 3. DATAFLASH VALUES (continued)

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units |
|-----------|---------------|--------------------|--------|-----------------|-----------|-----------|-----------|---------------|-----------|
| | | | 22 | xCell1 R_a 10 | I2 | -32768 | 32767 | 315 | mΩ at 0°C |
| | | | 24 | xCell1 R_a 11 | I2 | -32768 | 32767 | 437 | mΩ at 0°C |
| | | | 26 | xCell1 R_a 12 | I2 | -32768 | 32767 | 651 | mΩ at 0°C |
| | | | 28 | xCell1 R_a 13 | I2 | -32768 | 32767 | 1001 | mΩ at 0°C |
| | | | 30 | xCell1 R_a 14 | I2 | -32768 | 32767 | 1458 | mΩ at 0°C |
| Ra Table | 94 | R_a2x | 0 | xCell2 R_a flag | H2 | 0x0000 | 0xffff | 0xffff | |
| | | | 2 | xCell2 R_a 0 | I2 | -32768 | 32767 | 160 | mΩ at 0°C |
| | | | 4 | xCell2 R_a 1 | I2 | -32768 | 32767 | 166 | mΩ at 0°C |
| | | | 6 | xCell2 R_a 2 | I2 | -32768 | 32767 | 153 | mΩ at 0°C |
| | | | 8 | xCell2 R_a 3 | I2 | -32768 | 32767 | 151 | mΩ at 0°C |
| | | | 10 | xCell2 R_a 4 | I2 | -32768 | 32767 | 145 | mΩ at 0°C |
| | | | 12 | xCell2 R_a 5 | I2 | -32768 | 32767 | 152 | mΩ at 0°C |
| | | | 14 | xCell2 R_a 6 | I2 | -32768 | 32767 | 176 | mΩ at 0°C |
| | | | 16 | xCell2 R_a 7 | I2 | -32768 | 32767 | 204 | mΩ at 0°C |
| | | | 18 | xCell2 R_a 8 | I2 | -32768 | 32767 | 222 | mΩ at 0°C |
| | | | 20 | xCell2 R_a 9 | I2 | -32768 | 32767 | 254 | mΩ at 0°C |
| | | | 22 | xCell2 R_a 10 | I2 | -32768 | 32767 | 315 | mΩ at 0°C |
| | | | 24 | xCell2 R_a 11 | I2 | -32768 | 32767 | 437 | mΩ at 0°C |
| | | | 26 | xCell2 R_a 12 | I2 | -32768 | 32767 | 651 | mΩ at 0°C |
| 28 | xCell2 R_a 13 | I2 | -32768 | 32767 | 1001 | mΩ at 0°C | | | |
| 30 | xCell2 R_a 14 | I2 | -32768 | 32767 | 1458 | mΩ at 0°C | | | |
| Ra Table | 95 | R_a3x | 0 | xCell3 R_a flag | H2 | 0x0000 | 0xffff | 0xffff | |
| | | | 2 | xCell3 R_a 0 | I2 | -32768 | 32767 | 160 | mΩ at 0°C |
| | | | 4 | xCell3 R_a 1 | I2 | -32768 | 32767 | 166 | mΩ at 0°C |
| | | | 6 | xCell3 R_a 2 | I2 | -32768 | 32767 | 153 | mΩ at 0°C |
| | | | 8 | xCell3 R_a 3 | I2 | -32768 | 32767 | 151 | mΩ at 0°C |
| | | | 10 | xCell3 R_a 4 | I2 | -32768 | 32767 | 145 | mΩ at 0°C |
| | | | 12 | xCell3 R_a 5 | I2 | -32768 | 32767 | 152 | mΩ at 0°C |
| | | | 14 | xCell3 R_a 6 | I2 | -32768 | 32767 | 176 | mΩ at 0°C |
| | | | 16 | xCell3 R_a 7 | I2 | -32768 | 32767 | 204 | mΩ at 0°C |
| | | | 18 | xCell3 R_a 8 | I2 | -32768 | 32767 | 222 | mΩ at 0°C |
| | | | 20 | xCell3 R_a 9 | I2 | -32768 | 32767 | 254 | mΩ at 0°C |
| | | | 22 | xCell3 R_a 10 | I2 | -32768 | 32767 | 315 | mΩ at 0°C |
| | | | 24 | xCell3 R_a 11 | I2 | -32768 | 32767 | 437 | mΩ at 0°C |
| | | | 26 | xCell3 R_a 12 | I2 | -32768 | 32767 | 651 | mΩ at 0°C |
| 28 | xCell3 R_a 13 | I2 | -32768 | 32767 | 1001 | mΩ at 0°C | | | |
| 30 | xCell3 R_a 14 | I2 | -32768 | 32767 | 1458 | mΩ at 0°C | | | |
| PF Status | 96 | Device Status Data | 0 | PF Flags 1 | H2 | 0x0000 | 0xffff | 0x0000 | |
| | | | 2 | Fuse Flag | H2 | 0x0000 | 0xffff | 0x0000 | |
| | | | 4 | PF Voltage | U2 | 0 | 65535 | 0 | mV |
| | | | 6 | PF C4 Voltage | U2 | 0 | 9999 | 0 | mV |
| | | | 8 | PF C3 Voltage | U2 | 0 | 9999 | 0 | mV |
| | | | 10 | PF C2 Voltage | U2 | 0 | 9999 | 0 | mV |
| | | | 12 | PF C1 Voltage | U2 | 0 | 9999 | 0 | mV |
| | | | 14 | PF Current | I2 | -32768 | 32767 | 0 | mA |
| | | | 16 | PF Temperature | U2 | 0 | 9999 | 0 | 0.1°K |
| | | | 18 | PF Batt Stat | H2 | 0x0000 | 0xffff | 0x0000 | |
| | | | 20 | PF RC-mAh | U2 | 0 | 65535 | 0 | mAh |
| | | | 22 | PF RC-10mWh | U2 | 0 | 65535 | 0 | 10mWh |
| 24 | PF Chg Status | H2 | 0x0000 | 0xffff | 0x0000 | | | | |

Table 3. DATAFLASH VALUES (continued)

| Class | Subclass ID | Subclass | Offset | Name | Data Type | Min Value | Max Value | Default Value | Units |
|-------------|-------------|------------|--------|----------------------|-----------|------------|-----------|---------------|------------------|
| | | | 26 | PF Safety Status | H2 | 0x0000 | 0xffff | 0x0000 | |
| | | | 28 | PF Flags 2 | H2 | 0x0000 | 0xffff | 0x0000 | |
| PF Status | 97 | AFE Regs | 0 | AFE Status | H1 | 0x00 | 0xffff | 0x00 | |
| | | | 1 | AFE Output | H1 | 0x00 | 0xffff | 0x00 | |
| | | | 2 | AFE State | H1 | 0x00 | 0xffff | 0x00 | |
| | | | 3 | AFE Function | H1 | 0x00 | 0xffff | 0x00 | |
| | | | 4 | AFE Cell Select | H1 | 0x00 | 0xffff | 0x00 | |
| | | | 5 | AFE OLV | H1 | 0x00 | 0xffff | 0x00 | |
| | | | 6 | AFE OLT | H1 | 0x00 | 0xffff | 0x00 | |
| | | | 7 | AFE SCC | H1 | 0x00 | 0xffff | 0x00 | |
| | | | 8 | AFE SCD | H1 | 0x00 | 0xffff | 0x00 | |
| Calibration | 104 | Data | 0 | CC Gain | F4 | -1.00E+128 | 1.00E+128 | 0.471 | num |
| | | | 4 | CC Delta | F4 | -1.00E+128 | 1.00E+128 | 140500 | num |
| | | | 8 | Ref Voltage | I2 | 0 | 32767 | 24500 | 50 μ V |
| | | | 10 | AFE Corr | U2 | 0 | 65535 | 1288 | num |
| | | | 12 | AFE Pack Gain | U2 | 0 | 65535 | 30625 | num |
| | | | 14 | CC Offset | I2 | -32768 | 32767 | -12250 | num |
| | | | 16 | Board Offset | I1 | -128 | 127 | 0 | num |
| | | | 17 | Int Temp Offset | I1 | -128 | 127 | 0 | num |
| | | | 18 | Ext1 Temp Offset | I1 | -128 | 127 | 0 | num |
| | | | 19 | Ext2 Temp Offset | I1 | -128 | 127 | 0 | num |
| Calibration | 105 | Config | 0 | CC Current | U2 | 0 | 65535 | 3000 | mA |
| | | | 2 | Voltage Signal | U2 | 0 | 65535 | 16800 | mV |
| | | | 4 | Temp Signal | U2 | 0 | 65535 | 2980 | 0.1 $^{\circ}$ K |
| | | | 6 | CC Offset Time | U2 | 0 | 65535 | 250 | ms |
| | | | 8 | ADC Offset Time | U2 | 0 | 65535 | 32 | ms |
| | | | 10 | CC Gain Time | U2 | 0 | 65535 | 250 | ms |
| | | | 12 | Voltage Time | U2 | 0 | 65535 | 1984 | ms |
| | | | 14 | Temperature Time | U2 | 0 | 65535 | 32 | ms |
| | | | 17 | Cal Mode Timeout | U2 | 0 | 65535 | 38400 | sec/128 |
| Calibration | 106 | Temp Model | 0 | Ext Coef 1 | I2 | -32768 | 32767 | -28285 | Sec |
| | | | 2 | Ext Coef 2 | I2 | -32768 | 32767 | 20848 | Sec |
| | | | 4 | Ext Coef 3 | I2 | -32768 | 32767 | -7537 | Sec |
| | | | 6 | Ext Coef 4 | I2 | -32768 | 32767 | 4012 | Sec |
| | | | 8 | Ext Min AD | I2 | -32768 | 32767 | 0 | Sec |
| | | | 10 | Ext Max Temp | I2 | -32768 | 32767 | 4012 | Sec |
| | | | 12 | Int Coef 1 | I2 | -32768 | 32767 | 0 | Sec |
| | | | 14 | Int Coef 2 | I2 | -32768 | 32767 | 0 | Sec |
| | | | 16 | Int Coef 3 | I2 | -32768 | 32767 | -11136 | Sec |
| | | | 18 | Int Coef 4 | I2 | -32768 | 32767 | 5754 | Sec |
| | | | 20 | Int Min AD | I2 | -32768 | 32767 | 0 | Sec |
| | | | 22 | Int Max Temp | I2 | -32768 | 32767 | 5754 | Sec |
| Calibration | 107 | Current | 0 | Filter | U1 | 0 | 255 | 239 | mA |
| | | | 1 | Deadband | U1 | 0 | 255 | 3 | mA |
| | | | 2 | CC Deadband | U1 | 0 | 255 | 34 | nV+ |
| | | | 3 | CC Max Deadband | U1 | 0 | 255 | 5 | nV+ |
| | | | 4 | CC Deadband Sample | U2 | 0 | 65535 | 256 | num |
| | | | 6 | CC Max Offset Sample | U2 | 0 | 65535 | 64 | num |

Firmware Version Changes

bq20z80-V101 to bq20z80-V102 Changes

Table 4. CHANGE DETAILS

| CHANGE | bq0z80-V102 | bq20z80-V101 | COMMENTS |
|--|--|--|---|
| Corrected to allow display to turn off when charging and button pushed. | LED display operates correctly during charging. | LED display would stay on until charging terminated after the button was pushed. Only occurs when LED display not configured to be always on during charging. | Correct operation of the LED display under all conditions |
| Allow negative LED thresholds to permit LED alarms to be disabled | Configuring negative LED alarm threshold disables LED alarm functionality. | Feature not available | Allow better customization |
| Allow zero values for ALARM and CHARGING LED blink rates to disable them | Configuring zero value for the LED blink rates disables them. | Feature not available | Allow better customization |
| Restore initialization of dodcharge in relaxed state so that the correct dodcharge value is used in capacity estimation | dodcharge initialized to the correct value | dodcharge value set to zero | Improved gauging accuracy with correct initialization of dodcharge value. |
| Only clear offset calibration flag when SMBus lines go high. | Prevents offset calibration occurring just because a safety condition occurs and then clears when the SMBus lines are low. | Offset calibration occurs multiple times if safety condition occurs when SMBus lines are low. | More appropriate period between offset calibrations when SMBus lines are low. |
| Change so that setting AFE Fail Limit to zero disables PF_AFE_C | Configurable option to allow disabling PF_AFE_C trigger | Feature not available. | Allow better customization |
| Enable LED display to turn off after charge termination and if SMBus lines are detected low and LEDs enabled during charging. | LED display turns off after charge termination. | LED display stays on when charging terminates after SMBus lines are detected low. | Correct operation of the LED display under all conditions |
| Set charge FET state immediately when entering sleep | Charge FET state set correctly, immediately after entering sleep | The CHG FET would not get set to the correct state for sleep until the first voltage measurement. | Quicker transition of FET to the correct state in sleep |
| Change <i>DF:Operation Cfg B [CCT = 0]</i> , so that <i>SBS.CycleCount()</i> threshold is in mA, not in % of FCC | Data flash default bases <i>SBS.CycleCount()</i> calculation on mA and not % of FCC | <i>DF:Operation Cfg B [CCT = 1]</i> , making the default <i>SBS.CycleCount()</i> calculation to be based on % of FCC | Data flash default changed to reflect common customer usage |
| When <i>DF:Operation Cfg B [CCT = 1]</i> , so that <i>SBS.CycleCount()</i> threshold is % of FCC, then <i>DF:CC Threshold</i> is used as a minimum for the <i>SBS.CycleCount()</i> threshold | Use <i>DF:CC Threshold</i> as the minimum to prevent rapid incrementing of the <i>SBS.CycleCount()</i> , damaging the data flash | Small or negative <i>SBS.Full Charge Capacity()</i> values (should not occur under normal operation) from causing the <i>SBS.CycleCount()</i> incrementing rapidly, potentially damaging the data flash | Improved system reliability |
| When exiting the relaxed state to sleep, the initial charge capacity is correctly calculated | Corrected initial charge capacity calculation to be accurate when exiting relaxed state to sleep | If the relaxed state was exited to sleep after a valid DOD measurement (30-minute default value), then the initial charge capacity would not be recalculated and would result in an incorrect FCC value if the sleep state was exited before another valid DOD measurement (30-minute default value) | More reliable <i>SBS:FullChargeCapacity()</i> calculation under all system conditions |

Table 4. CHANGE DETAILS (continued)

| CHANGE | bq0z80-V102 | bq20z80-V101 | COMMENTS |
|--|--|--|---|
| Correct update of Remcap in relaxed state to use passed charge | Charge or discharge current accumulated in a relaxed state used to update Remcap | If the relaxed state was exited after the accumulation of significant charge or discharge current (over at most 100 seconds with default values), the RemCap and FCC would be in error by this charge. This is only significant if the relaxed state can exist with significant current as determined by application settings. | More reliable <i>SBS:FullChargeCapacity()</i> <i>SBS:RemainingCapacity()</i> calculation under all system conditions |
| Implement disable of resistance update based on accumulative scale. If the product of 15 consecutive (default value) resistance scale factors is less than 0.5 or more than 1.5, then resistance update is disabled until the next valid soc measurement. Sets bit 2 of Operation Status to indicate resistance update disabled. | Prevent invalid soc values from causing incorrect resistance updates | Incorrect resistance updates that could result from invalid soc values | More reliable resistance updates under all system conditions |
| Implement disable of resistance update based on estimated capacity error. Sets bit 2 of Operation Status to indicate resistance update disabled. | Prevent invalid soc values from causing incorrect resistance updates | Incorrect resistance updates that could result from invalid soc values | More reliable resistance updates under all system conditions |
| Disable Qmax increment if due to Grid 14 and exit of discharge | Prevent unnecessary Qmax increments | Qmax increments can occur due to Grid 14 and exit of discharge | Improved Qmax data reliability under all system conditions. |
| Drive all unused pins low | Provides better ESD immunity | Not all unused pins driven low | Improved ESD immunity |
| Initial charge capacity calculation when dod0 is measured in the overdischarged state is corrected | Overdischarged state does not affect the accuracy of FCC calculations | An incorrect initial charge capacity affects FCC that is calculated during discharge or a Qmax update. If FCC is not changed by a Qmax update, then reported RemainingCapacity could be negative after 5 hours of relaxation | More reliable <i>SBS:FullChargeCapacity()</i> <i>SBS:RemainingCapacity()</i> calculation under all system conditions |
| Correct calculation of FCC and RemCap when dod0 is taken when the battery is overdischarged or overcharged. This allows RemCap to go negative, or greater than FCC (though is only reported from 0 - FCC). | Overcharged/Overdischarged does not affect the accuracy of FCC and RemCap calculations | The RemainingCapacity will increment (or decrement) during charging (discharging) even when the battery is in an overdischarged (overcharged) state. | More reliable <i>SBS:FullChargeCapacity()</i> <i>SBS:RemainingCapacity()</i> calculation under all system conditions |
| Change cell imbalance <i>DF:Battery Rest Time</i> from 1 byte to 2 bytes and set the default value to 1800 seconds | New feature providing improved customization | Feature not available | Improved customization for Cell Imbalance detection |
| Use upper and lower limit for resistance accumulative scale. Set default values to 300% and 30%. | | | More reliable resistance updates under all system conditions |
| Add <i>DF:CF MaxError limit</i> for setting <i>SBS.BatteryMode() [CONDITION FLAG]</i> . Set default value to 100%. | New feature providing improved customization | Feature not available | Improved customization |

Table 4. CHANGE DETAILS (continued)

| CHANGE | bq0z80-V102 | bq20z80-V101 | COMMENTS |
|--|--|---|--|
| Use <i>SBS.AtRate()</i> , <i>UserRate</i> and <i>C/5</i> rate for relaxed capacity calculation, respectively, if set by Load Select; otherwise, use previous rate. | | | More reliable <i>SBS:FullChargeCapacity()</i> <i>SBS:RemainingCapacity()</i> calculation under all system conditions |
| Correct Host Watchdog from being reset by broadcasts | Host Watchdog functionality not affected by alarm or charger broadcasts | Host Watchdog reset by alarm or charger broadcasts | Reliable Host Watchdog functionality under all system conditions |
| The voltage table chemistry ID can be read by writing 0x0008 to <i>ManufacturerAccess</i> and then reading from <i>ManufacturerAccess</i> . The default chemistry ID is 0x0100 | New feature providing more information | Feature not available | Improved information access |
| <i>SBS.BatteryMode()</i> is initialized on high transition of the SMBus lines to <i>DF:InitBatteryMode</i> , instead of always clearing <i>SBS.BatteryMode()</i> defined bits on high transition of the SMBus lines. | Customization allows for preserving <i>SBS.BatteryMode()</i> settings through SMBus line transitions | Feature not available | Improved customization |
| Broadcast timers are set correctly on high transition of SMBus lines. The timers are set to 10 seconds on high transition of SMBus lines. | Broadcast timer accurate regardless of CC offset calibration or entry to sleep | Broadcast timer accuracy required a CC offset calibration and entry to sleep. | Improved broadcast timing accuracy to meet Smart Battery Data spec |

bq20z80 to bq20z80-V101 Changes

| CHANGE | bq20z80 | bq20z80-V101 | COMMENTS |
|---|---|---|---|
| Added authentication (optional SBS command 0x2f) | Command 0x2f has no function and is not acknowledged. | Command 0x2f is the <i>SBS.Authenticate()</i> command to the bq20z80 to begin the SHA1 authentication. | Additional feature to enable host to authenticate the battery |
| Added Cell Balancing | Cell balancing not available | Added State of Charge cell balancing algorithm | Additional feature to enable longer lifetime of battery |
| Added charge fault FET Enable register | When charge faults occur, FET action is taken. | When charge faults occur, FET action is taken if enabled in <i>DF:FET Enable</i> register. | Adds flexibility to system interaction |
| Added pulse compensation for end of discharge | Applications with pulsed current loads and minimum voltage requirements can have less <i>RemainingCapacity</i> than reported. | The voltage pulses caused by pulsed current loads are measured and used to better estimate <i>RemainingCapacity</i> . | Added additional feature to improve capacity prediction |
| Added <i>SBS.BatteryStatus()</i> [TDA, FD] voltage thresholds | <i>SBS.BatteryStatus()</i> [TDA, FD] are only set on SBS.RSOC, detection of charge termination or faults | <i>SBS.BatteryStatus()</i> [TDA, FD] are now set and cleared based on <i>SBS.Voltage()</i> | Adds flexibility to system interaction |
| Added option for LEDs in series with current source | LED display is only in parallel. | LED display is available in series (with current source) or parallel. | Adds capability for higher brightness LEDs |
| Configured pin 7 as active high fuse blow | Pin 7 is not connected. | Pin 7 is now an active high reflection of SAFE (pin 12). | Adds flexibility to choose different circuits driven by the permanent failure signal |
| Added State of Health calculation (command 0x4f) | Command 0x4f has no function and is not acknowledged. | Command 0x4f is the <i>SBS.StateOfHealth()</i> command where SOH is the ratio of <i>SBS.DesignCapacity()</i> to <i>SBS.FullChargeCapacity()</i> . | Additional feature to allow host to easily determine health of the battery |
| Added Synchronization of <i>SBS.RemainingCapacity()</i> to <i>SBS.FullChargeCapacity()</i> at charge taper termination. | <i>SBS.RemainingCapacity()</i> is not affected and could be < 100% at charge termination. | If <i>DF:Operation Cfg</i> [RMFCC] is set then <i>SBS.RemainingCapacity()</i> is updated to the value of <i>SBS.FullChargeCapacity()</i> at charge termination. | Adds option to enable charge synchronization in order to display <i>RelativeStateOfCharge</i> as 100% at charge termination |

SLUS681B – NOVEMBER 2005 – REVISED JANUARY 2007

| CHANGE | bq20z80 | bq20z80-V101 | COMMENTS |
|---|---|---|--|
| Improved thermal model | A preliminary thermal mode was used. | An updated thermal model is used. | Improved thermal compensation of Impedance Track™ algorithm |
| Improved cell capacity measurement by limiting valid temperature ranges | Valid voltage measurements for cell capacity estimation can occur at any temperature. | Valid voltage measurements for cell capacity estimation must occur within a defined temperature range. | Improves capacity estimation |
| Improved cell capacity measurement | After a full reset, it may take several minutes for voltage reading to settle to the most accurate reading. | Settling time of voltage measurements after a full reset is reduced. | Improves initial voltage reading accuracy |
| Improved default resistance tables | A preliminary default resistance mode was used. | An updated default resistance mode is used. | Improved thermal accuracy of Impedance Track™ algorithm |
| Prevented lifetime updates until IT is enabled | Data flash lifetime data is updated under all conditions. | Data flash lifetime data is not updated until Impedance Track™ is enabled. | Improves suitability of lifetime data |
| Aligned SBS.RemainingCapacity() with DF.Terminate Voltage | SBS.RemainingCapacity() could be above zero when SBS.Voltage() reaches DF.Terminate Voltage. | Forces SBS.RemainingCapacity() to zero when SBS.Voltage() is below terminate voltage | Improves alignment between reporting and system status |
| Disabled LEDs for undervoltage conditions | When SBS.OperationStatus() [CUV or PUV] is set, then the LED display could be activated. | When SBS.OperationStatus() [CUV or PUV] is set, the LED display is disabled. | Reduces risk of deeply discharging the battery |
| Clear SBS.BatteryStatus() [RCA] when not SBS.BatteryStatus() [DSG] | SBS.BatteryStatus() [RCA] is not cleared when SBS.BatteryStatus() [DSG] is cleared. | SBS.BatteryStatus() [RCA] is now cleared when SBS.BatteryStatus() [DSG] is cleared. | Corrected to meet SBS specification |
| Allowed sleep mode for undervoltage conditions | When SBS.OperationStatus() [CUV or PUV] is set, then entry to sleep mode is disabled. | When SBS.OperationStatus() [CUV or PUV] is set, then entry to sleep mode is allowed. | Reduces risk of deeply discharging the battery |
| Improvements made to Lifetime data | Does not save maximum and minimum lifetime AverageCurrent or AveragePower. Only saves lifetime data when new values exceed old values by defined delta values | Saves maximum and minimum lifetime AverageCurrent and AveragePower. Lifetime data is saved after a defined period of time even if new values do not exceed old values by defined delta values | Improves lifetime data |
| Changes made to pulse charging | Voltages for pulse charging are sampled once a second. | Voltages for pulse charging are sampled 4 times a second. | Improves pulse charging |
| Changes made to charging timeouts | The precharge timeout timer runs when the charging current is below a defined threshold; so, it is possible that the precharge timer will run during charging taper current and cause an undesired precharge timeout during charging taper. | The fast charge and precharge timeout timers only run when precharging or charging, as indicated by FCHG and PCHG bits in ChargingStatus. | Improves operation of fast charge and precharge timeout timers |
| Changes made to discharge faults | Discharging fault is indicated whenever BatteryStatus [TDA] is set. Current discharging fault is not indicated for current faults detect by AFE. Separate discharging faults are indicated for voltage and temperature. | Discharging fault is indicated for any safety condition resulting in turning off the discharge FET. Current discharging fault is indicated for all detected overcurrent conditions, including overcurrent detected by AFE. Temperature and voltage discharge faults are not indicated separately. | Improves indication of discharging fault conditions |
| Improvements made to calibration functions | Voltage calibration functions may cause error in voltage calibration of several millivolts. | Voltage calibration functions are capable of accuracy within 1 millivolt. | Improved voltage calibration accuracy |
| Protect against simultaneous writes to data flash | A SMBus-initiated data flash write may occur at the same time as a data flash write initiated by the AGG, which may cause a data flash write error. | A SMBus-initiated data flash write cannot occur at the same time as any other data flash write. | Increased robustness of data flash writes |
| Corrected SBS.ManufacturerAccess() access of silicon revision | SBS.ManufacturerAccess() access of silicon revision is not functional. | SBS.ManufacturerAccess() access of silicon revision is functional. | Allows host to determine bq20z80 silicon revision |
| Corrected data flash checksum operation | The data flash checksum includes non-accessible portions of the data flash that change when writing the data flash checksum, invalidating the checksum. | The data flash checksum only includes data flash that does not change when writing an updated data flash checksum. | Data flash checksum operation works correctly. |
| Corrections made to LED display | Fixed LED thresholds cannot be selected. | Fixed LED thresholds can be selected. | Correct operation of LED threshold settings |
| Erroneous readings are corrected that occurred after offset calibration when sleep mode is not entered. | Erroneous SBS voltage, current, and temperature readings occur after current offset calibration if sleep mode is not entered, corrupting the lifetime data. | No erroneous SBS voltage, current, and temperature readings occur after current offset calibration if sleep mode is not entered. | Improve reliability of lifetime data |

| CHANGE | bq20z80 | bq20z80-V101 | COMMENTS |
|--|---|--|--|
| Corrected the length of <code>SBS.ManufacturerData()</code> command | <code>SBS.ManufacturerData()</code> returned additional data not specified in the data sheet. | Only returns the appropriate data | Correct data set made available to host |
| Changed <code>DF:Charger Present</code> default voltage to 12000 mV | <code>DF:Charger Present</code> default was 16800 mV. | Default changed to 12000 mV. | More realistic default for most applications |
| Corrected LED display lock-up fault when exiting sleep with LEDs on | LED display locks up if LEDs are ON as the bq20z80 exits sleep mode. | LED display operates normally regardless of power state transitions. | Correct operation of the LED display under all conditions |
| Added report of any inability to write DFF as flash write error in calibration mode | If writing the data flash is not allowed either due to a permanent failure or low voltage, then no indication is given when attempting to write data flash in calibration mode. | The inability to write data flash in calibration mode is reported as a flash write error. | Improved calibration system interaction |
| Corrected issue of improperly clearing AFE faults | AFE faults were detected and the pack protected but the fault would be cleared up to three times at an interval of 250 milliseconds before the defined recovery requirements would apply. | AFE faults are correctly handled, including the flags. | Improved system interaction when faults occur |
| Modified code to save open-circuit voltage (OCV) data on IT enable only, not a full reset | OCV data was saved after a full reset which could have disturbed the OCV measurements if the battery was not in a completely relaxed state. | OCV tables are only updated when IT enabled, or the IT enable command is resent. | Improved OCV data reliability under all system conditions |
| Corrected range check for calibration of analog-to-digital converter (ADC) offset | In calibration mode, if the measurement ADC offset was out of range, no error would be reported. | In calibration mode, if the measurement ADC offset is out of range, an error is reported. | Improved calibration system interaction |
| Implemented a validation time for DOD0 | There is a possibility of erroneous DOD0 measurement if charge or discharge current occurs at the same time. | DOD0 measurement is not saved unless the battery remains in the relaxed state for a defined time after the DOD0 measurement is made. | More reliable <code>SBS.FullChargeCapacity()</code> and <code>SBS.RemainingCapacity</code> under all system conditions |
| Implemented a bounds limit to a QMAX change | QMAX changes are not limited to filter-bad readings. | QMAX changes are bounds limited to filter-bad readings. | More reliable <code>SBS.FullChargeCapacity()</code> and <code>SBS.RemainingCapacity</code> under all system conditions |
| Implemented a double hit for dv/dt detection for QMAX qualification | The dv/dt qualification for QMAX update requires only one sample to be valid. | The dv/dt qualification for QMAX update requires two samples to be valid. | More reliable <code>SBS.FullChargeCapacity()</code> and <code>SBS.RemainingCapacity()</code> under all system conditions |
| Corrected parameter update issue caused by exiting sleep mode during current measurement | If bq20z80 exits sleep during a current measurement, the SBS parameters do not update again until the pack enters and exits sleep mode again. | SBS parameter updates operate normally regardless of power state transitions. | Improved system interaction for sleep mode transitions |
| Implemented an option to leave charge FET on for a nonremovable pack in sleep mode, enabled by <code>DF:Operation Cfg B [NRCHG]</code> . | When <code>DF:Operation Cfg B [NR]</code> is set, then the CHG is turned off at entry to sleep mode. | When <code>DF:Operation Cfg B [NR, NRCHG]</code> are set, then the CHG remains on at entry to sleep mode. | Improved system interaction options |
| Modified code such that if QMAX has not been updated, old valid OCV readings are discarded when a new valid OCV reading is detected and the conditions for QMAX update do not exist. | Valid OCV is only discarded when all conditions for QMAX update are satisfied, but the accumulated error in the measured capacity exceeds 1% (default value). | If QMAX has been updated, the same conditions for discarding an OCV reading are the same as for the bq20z80. Otherwise, old OCV readings are discarded and new OCV readings are used when the conditions for a valid OCV reading exist, but the conditions for QMAX update do not exist. | Enables QMAX measurement for full charge or discharge for the first QMAX update, even if initial OCV measurement is made when battery is only partially charged. |
| Modified code such that if QMAX has not been updated, then for QMAX update to occur, the measured capacity must be greater than or equal to 90% (default value) of design capacity. | The measured capacity must be greater than 20% (default value) or a value as determined from the QMAX update filter constant for a QMAX update to occur. | For the first QMAX, the measured capacity must be greater than 90% (default value) for a QMAX update to occur. If QMAX update has occurred the conditions for measured capacity are the same as for the bq20z80. | Improved QMAX data reliability for the first update of QMAX |
| Default minimum passed charge for QMAX update has been changed from 20% to 37% | Internal flash value of Min Passed Charge is 20%. The default setting for the QMAX update filter constant of 64 means actual Min Passed Charge for QMAX update is 25%. | Internal flash value of Min Passed Charge is 37%. This 37% is consistent with the QMAX update filter constant of 96. | Improved QMAX data reliability under all system conditions. |
| Default QMAX update filter constant has been changed from 64 to 94. | Internal flash value of QMAX update filter is 64. | Internal flash value of QMAX update filter is 94. | Improved QMAX data reliability under all system conditions. |
| QMAX values for nonexistent cells will be updated to Design Capacity. | <code>DF:Qmax Cell 2..4</code> written with random values if not used when QMAX is updated | <code>DF:Qmax Cell 2..4</code> are updated to = <code>DF:Design Capacity</code> if not used when QMAX is updated. | Ensure all QMAX values are reasonable, even if not used |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|--------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|---------|
| BQ20Z80DBT-V102 | NRND | TSSOP | DBT | 38 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | 20Z80DBT | |
| BQ20Z80DBTR-V102 | NRND | TSSOP | DBT | 38 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | 20Z80DBT | |
| BQ20Z80DBTR-V102G4 | NRND | TSSOP | DBT | 38 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | 20Z80DBT | |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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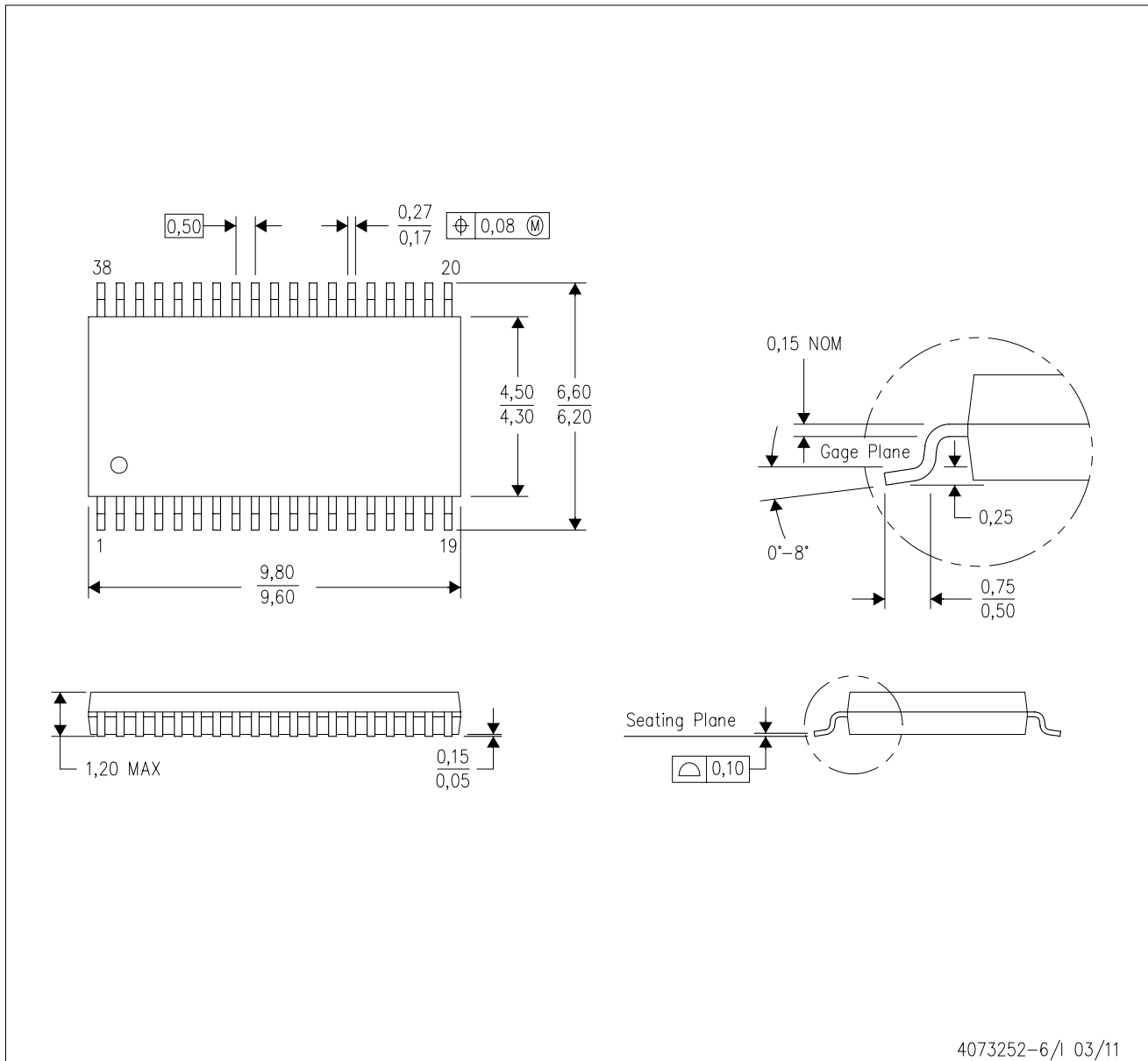
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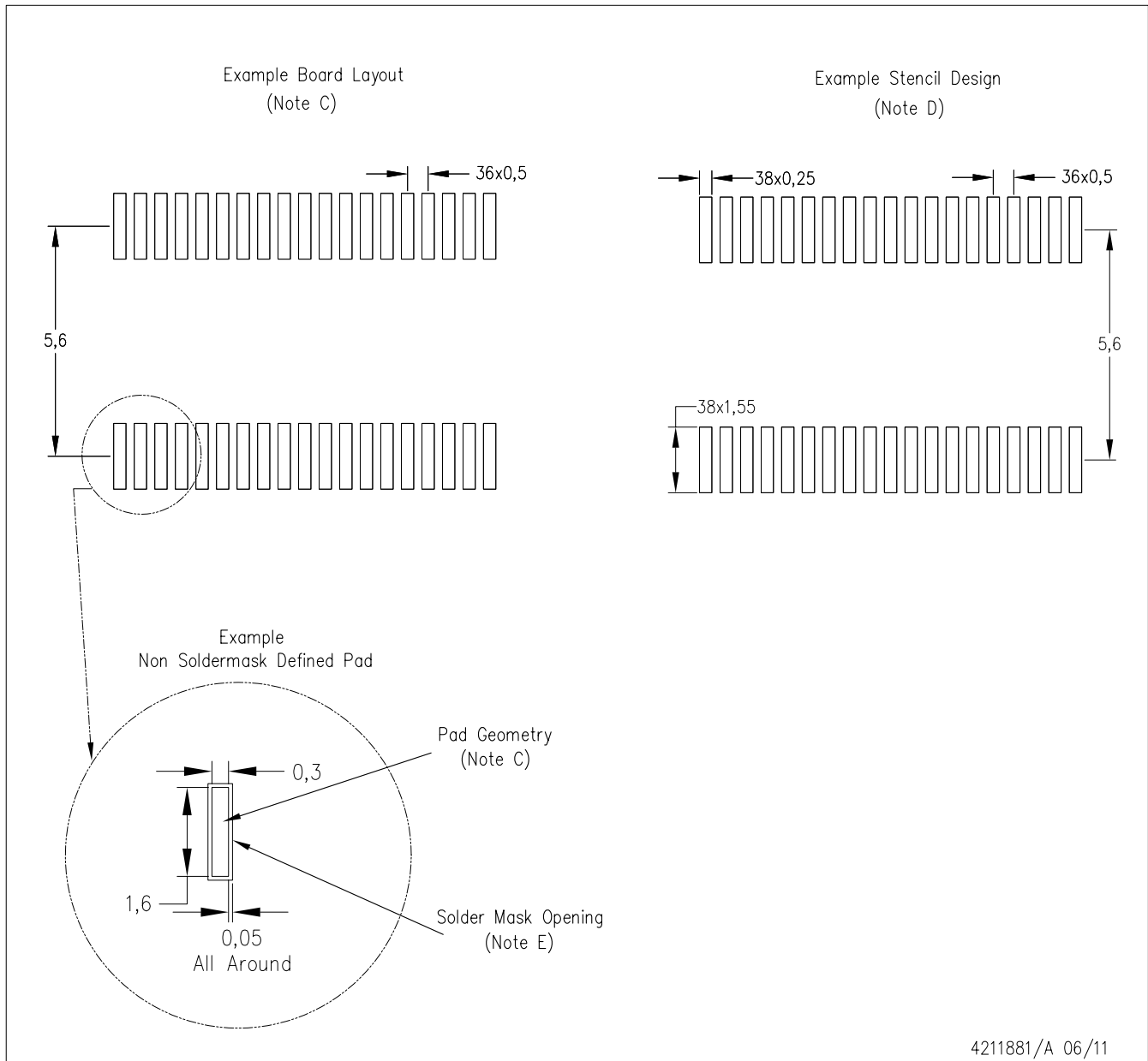
MECHANICAL DATA

DBT (R-PDSO-G38)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - Falls within JEDEC MO-153.



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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